TLV431x Low-Voltage Adjustable Precision Shunt Regulator

1 Features

- Low-Voltage Operation, V_{REF} = 1.24 V
- Adjustable Output Voltage, V_O = V_{REF} to 6 V
- Reference Voltage Tolerances at 25°C
  - 0.5% for TLV431B
  - 1% for TLV431A
  - 1.5% for TLV431
- Typical Temperature Drift
  - 4 mV (0°C to 70°C)
  - 6 mV (–40°C to 85°C)
  - 11 mV (–40°C to 125°C)
- Low Operational Cathode Current, 80 µA Typ
- 0.25-Ω Typical Output Impedance
- Ultra-Small SC-70 Package Offers 40% Smaller Footprint Than SOT-23-3
- See TLVH431 and TLVH432 for:
  - Wider V_{KA} (1.24 V to 18 V) and I_K (80 mA)
  - Additional SOT-89 Package
  - Multiple Pinouts for SOT-23-3 and SOT-89 Packages
- On Products Compliant to MIL-PRF-38535, All Parameters Are Tested Unless Otherwise Noted. On All Other Products, Production Processing Does Not Necessarily Include Testing of All Parameters.

2 Applications

- Adjustable Voltage and Current Referencing
- Secondary Side Regulation in Flyback SMPSs
- Zener Replacement
- Voltage Monitoring
- Comparator with Integrated Reference

3 Description

The TLV431 device is a low-voltage 3-terminal adjustable voltage reference with specified thermal stability over applicable industrial and commercial temperature ranges. Output voltage can be set to any value between V_{REF} (1.24 V) and 6 V with two external resistors (see Figure 20). These devices operate from a lower voltage (1.24 V) than the widely used TL431 and TL1431 shunt-regulator references.

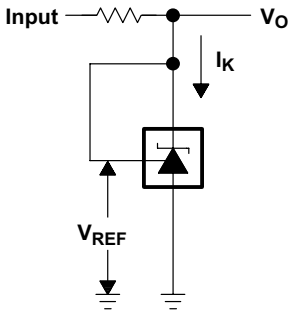
When used with an optocoupler, the TLV431 device is an ideal voltage reference in isolated feedback circuits for 3-V to 3.3-V switching-mode power supplies. These devices have a typical output impedance of 0.25 Ω. Active output circuitry provides a very sharp turn-on characteristic, making them excellent replacements for low-voltage Zener diodes in many applications, including on-board regulation and adjustable power supplies.

Device Information(1)

PART NUMBER	PACKAGE (PIN)	BODY SIZE (NOM)
TLV431x	SOT-23 (3)	2.90 mm x 1.30 mm
	SOT-23 (5)	2.90 mm x 1.60 mm
	SC70 (6)	2.00 mm x 1.25 mm
	TO-92 (3)	4.30 mm × 4.30 mm
	SOIC (8)	4.90 mm x 3.90 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

4 Simplified Schematic



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5 Revision History

Changes from Revision U (January 2014) to Revision V **Page**

- Added *Applications*, *Device Information* table, *Pin Functions* table, *ESD Ratings* table, *Thermal Information* table, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section. ... 1
- Moved *Typical Characteristics* into *Specifications* section. ... 8
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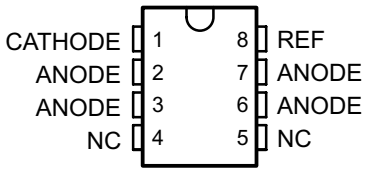
- Moved *Typical Characteristics* into *Specifications* section. ... 14

Changes from Revision T (June 2007) to Revision U **Page**

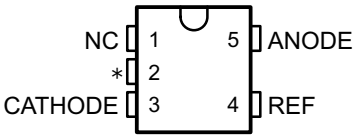
- Updated document to new TI data sheet format. ... 1
- Deleted *Ordering Information* table. ... 1
- Updated *Features*. ... 1

6 Pin Configuration and Functions

D (SOIC) PACKAGE
(TOP VIEW)

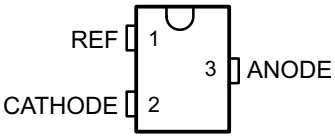


DBV (SOT-23-5) PACKAGE
(TOP VIEW)

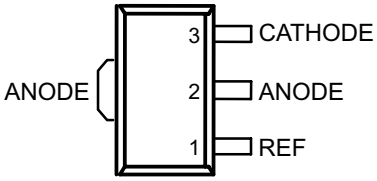


NC − No internal connection
∗ For TLV431, TLV431A: NC − No internal connection
∗ For TLV431B: Pin 2 is attached to Substrate and must be connected to ANODE or left open.

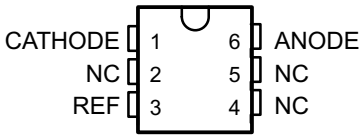
DBZ (SOT-23-3) PACKAGE
(TOP VIEW)



PK (SOT-89) PACKAGE
(TOP VIEW)

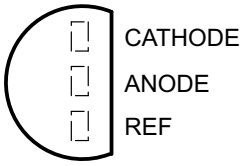


DCK (SC-70) PACKAGE
(TOP VIEW)



NC − No internal connection

LP (TO-92/TO-226) PACKAGE
(TOP VIEW)



Pin Functions

PIN							TYPE	DESCRIPTION
NAME	DBZ	DBV	PK	D	LP	DCK		
CATHODE	2	3	3	1	1	1	I/O	Shunt Current/Voltage input
REF	1	4	1	8	3	3	I	Threshold relative to common anode
ANODE	3	5	2	2, 3, 6, 7	2	6	O	Common pin, normally connected to ground
NC	—	1	—	4, 5	—	2, 4, 5	I	No Internal Connection
*	—	2	—	—	—	—	I	Substrate Connection

7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

		MIN	MAX	UNIT
V_{KA}	Cathode voltage(2)		7	V
I_K	Continuous cathode current range	–20	20	mA
I_{ref}	Reference current range	–0.05	3	mA
	Operating virtual junction temperature		150	°C
T_{stg}	Storage temperature range	–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) Voltage values are with respect to the anode terminal, unless otherwise noted.

7.2 ESD Ratings

PARAMETER		DEFINITION	VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins(1)	±2000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins(2)	±1000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Thermal Information

THERMAL METRIC(1)		TLV431x						UNIT
		DCK	D	PK	DBV	DBZ	LP	
		6 PINS	8 PINS	3 PINS	5 PINS	3 PINS	3 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	87	97	52	206	206	140	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	259	39	9	131	76	55	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report (SPRA953).

7.4 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{KA}	Cathode voltage		V_{REF}	6	V
I_K	Cathode current		0.1	15	mA
T_A	Operating free-air temperature range	TLV431_C	0	70	°C
		TLV431_I	–40	85	
		TLV431_Q	–40	125	

7.5 Electrical Characteristics for TLV431

at 25°C free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS			TLV431 MIN	TLV431 TYP	TLV431 MAX	UNIT
V_{REF}	Reference voltage	$V_{KA} = V_{REF}$, I_K = 10 mA	T_A = 25°C		1.222	1.24	1.258	V
			T_A = full range[1] (see Figure 19)	TLV431C	1.21		1.27	
				TLV431I	1.202		1.278	
				TLV431Q	1.194		1.286	
$V_{REF(dev)}$	V_{REF} deviation over full temperature range[2]	$V_{KA} = V_{REF}$, I_K = 10 mA[1] (see Figure 19)		TLV431C		4	12	mV
				TLV431I		6	20	
				TLV431Q		11	31	
$\frac{\Delta V_{REF}}{\Delta V_{KA}}$	Ratio of V_{REF} change in cathode voltage change	$V_{KA} = V_{REF}$ to 6 V, I_K = 10 mA (see Figure 20)				–1.5	–2.7	mV/V
I_{ref}	Reference terminal current	I_K = 10 mA, R1 = 10 kΩ, R2 = open (see Figure 20)				0.15	0.5	µA
$I_{ref(dev)}$	I_{ref} deviation over full temperature range[2]	I_K = 10 mA, R1 = 10 kΩ, R2 = open[1] (see Figure 20)		TLV431C		0.05	0.3	µA
				TLV431I		0.1	0.4	
				TLV431Q		0.15	0.5	
$I_{K(min)}$	Minimum cathode current for regulation	$V_{KA} = V_{REF}$ (see Figure 19)		TLV431C/I		55	80	µA
				TLV431Q		55	100	
$I_{K(off)}$	Off-state cathode current	V_{REF} = 0, V_{KA} = 6 V (see Figure 21)				0.001	0.1	µA
$\|z_{KA}\|$	Dynamic impedance[3]	$V_{KA} = V_{REF}$, f ≤ 1 kHz, I_K = 0.1 mA to 15 mA (see Figure 19)				0.25	0.4	Ω

(1) Full temperature ranges are –40°C to 125°C for TLV431Q, –40°C to 85°C for TLV431I, and 0°C to 70°C for TLV431C.

(2) The deviation parameters $V_{REF(dev)}$ and $I_{ref(dev)}$ are defined as the differences between the maximum and minimum values obtained over the rated temperature range. The average full-range temperature coefficient of the reference input voltage, αV_{REF}, is defined as:

$$\left|\alpha V_{REF}\right|\left(\frac{ppm}{°C}\right) = \frac{\left(\frac{V_{REF(dev)}}{V_{REF}\left(T_A = 25°C\right)}\right) \times 10^6}{\Delta T_A}$$

where ΔT_A is the rated operating free-air temperature range of the device.

αV_{REF} can be positive or negative, depending on whether minimum V_{REF} or maximum V_{REF}, respectively, occurs at the lower temperature.

(3) The dynamic impedance is defined as $|z_{ka}| = \frac{\Delta V_{KA}}{\Delta I_K}$

When the device is operating with two external resistors (see Figure 20), the total dynamic impedance of the circuit is defined as:

$$|z_{ka}|' = \frac{\Delta V}{\Delta I} \approx |z_{ka}| \times \left(1 + \frac{R1}{R2}\right)$$

7.6 Electrical Characteristics for TLV431A

at 25°C free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS			TLV431A			UNIT
					MIN	TYP	MAX	
V_{REF}	Reference voltage	$V_{KA} = V_{REF}$, I_K = 10 mA	T_A = 25°C		1.228	1.24	1.252	V
			T_A = full range[1] (see Figure 19)	TLV431AC	1.221		1.259	
				TLV431AI	1.215		1.265	
				TLV431AQ	1.209		1.271	
$V_{REF(dev)}$	V_{REF} deviation over full temperature range[2]	$V_{KA} = V_{REF}$, I_K = 10 mA[1] (see Figure 19)		TLV431AC		4	12	mV
				TLV431AI		6	20	
				TLV431AQ		11	31	
$\frac{\Delta V_{REF}}{\Delta V_{KA}}$	Ratio of V_{REF} change in cathode voltage change	$V_{KA} = V_{REF}$ to 6 V, I_K = 10 mA (see Figure 20)				–1.5	–2.7	mV/V
I_{ref}	Reference terminal current	I_K = 10 mA, R1 = 10 kΩ, R2 = open (see Figure 20)				0.15	0.5	µA
$I_{ref(dev)}$	I_{ref} deviation over full temperature range[2]	I_K = 10 mA, R1 = 10 kΩ, R2 = open[1] (see Figure 20)		TLV431AC		0.05	0.3	µA
				TLV431AI		0.1	0.4	
				TLV431AQ		0.15	0.5	
$I_{K(min)}$	Minimum cathode current for regulation	$V_{KA} = V_{REF}$ (see Figure 19)		TLV431AC/AI		55	80	µA
				TLV431AQ		55	100	
$I_{K(off)}$	Off-state cathode current	V_{REF} = 0, V_{KA} = 6 V (see Figure 21)				0.001	0.1	µA
$\|z_{KA}\|$	Dynamic impedance[3]	$V_{KA} = V_{REF}$, f ≤ 1 kHz, I_K = 0.1 mA to 15 mA (see Figure 19)				0.25	0.4	Ω

(1) Full temperature ranges are –40°C to 125°C for TLV431Q, –40°C to 85°C for TLV431I, and 0°C to 70°C for TLV431C.

(2) The deviation parameters $V_{REF(dev)}$ and $I_{ref(dev)}$ are defined as the differences between the maximum and minimum values obtained over the rated temperature range. The average full-range temperature coefficient of the reference input voltage, αV_{REF}, is defined as:

$$\left|\alpha V_{REF}\right|\left(\frac{ppm}{°C}\right) = \frac{\left(\frac{V_{REF(dev)}}{V_{REF}\left(T_A = 25°C\right)}\right) \times 10^6}{\Delta T_A}$$

where ΔT_A is the rated operating free-air temperature range of the device.

αV_{REF} can be positive or negative, depending on whether minimum V_{REF} or maximum V_{REF}, respectively, occurs at the lower temperature.

(3) The dynamic impedance is defined as $|z_{ka}| = \frac{\Delta V_{KA}}{\Delta I_K}$

When the device is operating with two external resistors (see Figure 20), the total dynamic impedance of the circuit is defined as:

$$|z_{ka}|' = \frac{\Delta V}{\Delta I} \approx |z_{ka}| \times \left(1 + \frac{R1}{R2}\right)$$

7.7 Electrical Characteristics for TLV431B

at 25°C free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS			TLV431B MIN	TLV431B TYP	TLV431B MAX	UNIT
V_{REF}	Reference voltage	$V_{KA} = V_{REF}$, I_K = 10 mA	T_A = 25°C		1.234	1.24	1.246	V
			T_A = full range[1] (see Figure 19)	TLV431BC	1.227		1.253	
				TLV431BI	1.224		1.259	
				TLV431BQ	1.221		1.265	
$V_{REF(dev)}$	V_{REF} deviation over full temperature range[2]	$V_{KA} = V_{REF}$, I_K = 10 mA[1] (see Figure 19)		TLV431BC		4	12	mV
				TLV431BI		6	20	
				TLV431BQ		11	31	
$\frac{\Delta V_{REF}}{\Delta V_{KA}}$	Ratio of V_{REF} change in cathode voltage change	$V_{KA} = V_{REF}$ to 6 V, I_K = 10 mA (see Figure 20)				–1.5	–2.7	mV/V
I_{ref}	Reference terminal current	I_K = 10 mA, R1 = 10 kΩ, R2 = open (see Figure 20)				0.1	0.5	µA
$I_{ref(dev)}$	I_{ref} deviation over full temperature range[2]	I_K = 10 mA, R1 = 10 kΩ, R2 = open[3] (see Figure 20)		TLV431BC		0.05	0.3	µA
				TLV431BI		0.1	0.4	
				TLV431BQ		0.15	0.5	
$I_{K(min)}$	Minimum cathode current for regulation	$V_{KA} = V_{REF}$ (see Figure 19)				55	100	µA
$I_{K(off)}$	Off-state cathode current	V_{REF} = 0, V_{KA} = 6 V (see Figure 21)				0.001	0.1	µA
$\lvert z_{KA} \rvert$	Dynamic impedance[4]	$V_{KA} = V_{REF}$, f ≤ 1 kHz, I_K = 0.1 mA to 15 mA (see Figure 19)				0.25	0.4	Ω

(1) Full temperature ranges are –40°C to 125°C for TLV431Q, –40°C to 85°C for TLV431I, and 0°C to 70°C for TLV431C.

(2) The deviation parameters $V_{REF(dev)}$ and $I_{ref(dev)}$ are defined as the differences between the maximum and minimum values obtained over the rated temperature range. The average full-range temperature coefficient of the reference input voltage, αV_{REF}, is defined as:

$$\left|\alpha V_{REF}\right|\left(\frac{ppm}{°C}\right) = \frac{\left(\frac{V_{REF(dev)}}{V_{REF}\left(T_A = 25°C\right)}\right) \times 10^6}{\Delta T_A}$$

where ΔT_A is the rated operating free-air temperature range of the device.

αV_{REF} can be positive or negative, depending on whether minimum V_{REF} or maximum V_{REF}, respectively, occurs at the lower temperature.

(3) Full temperature ranges are –40°C to 125°C for TLV431Q, –40°C to 85°C for TLV431I, and 0°C to 70°C for TLV431C.

(4) The dynamic impedance is defined as $\left|z_{ka}\right| = \frac{\Delta V_{KA}}{\Delta I_K}$

When the device is operating with two external resistors (see Figure 20), the total dynamic impedance of the circuit is defined as:

$$\left|z_{ka}\right|' = \frac{\Delta V}{\Delta I} \approx \left|z_{ka}\right| \times \left(1 + \frac{R1}{R2}\right)$$

7.8 Typical Characteristics

Operation of the device at these or any other conditions beyond those indicated in the *Recommended Operating Conditions* table are not implied.

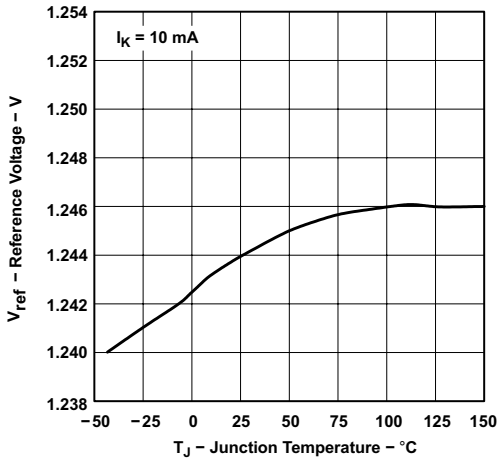


Figure 1. Reference Voltage vs Junction Temperature

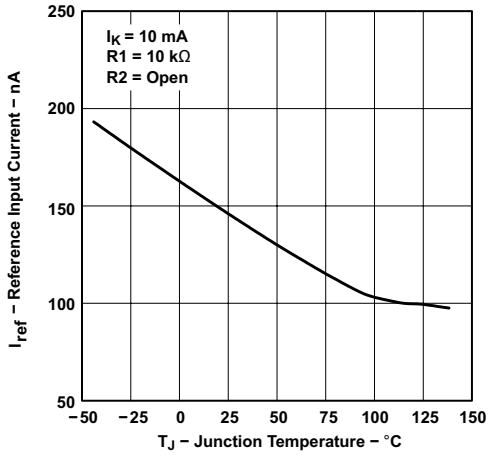


Figure 2. Reference Input Current vs Junction Temperature (for TLV431 and TLV431A)

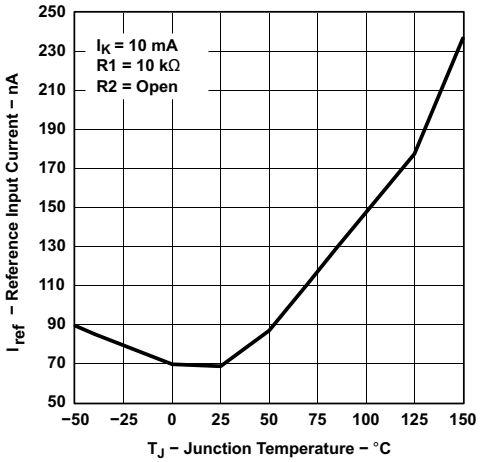


Figure 3. Reference Input Current vs Junction Temperature (for TLV431B)

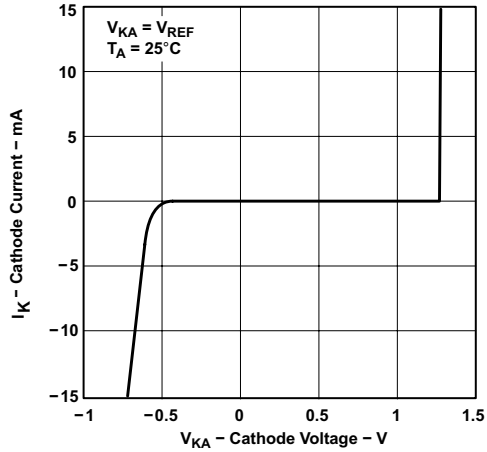


Figure 4. Cathode Current vs Cathode Voltage

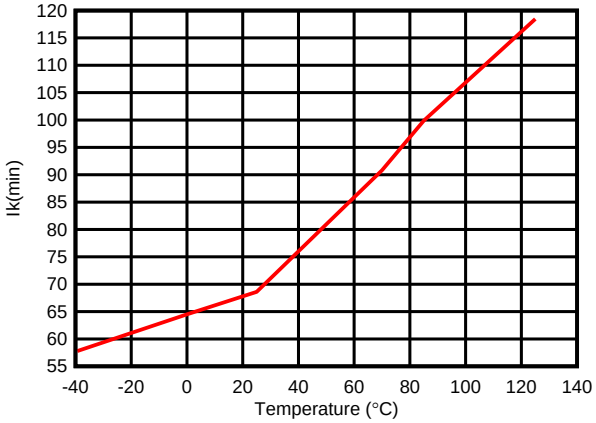


Figure 5. Minimum Cathode Current vs Temperature

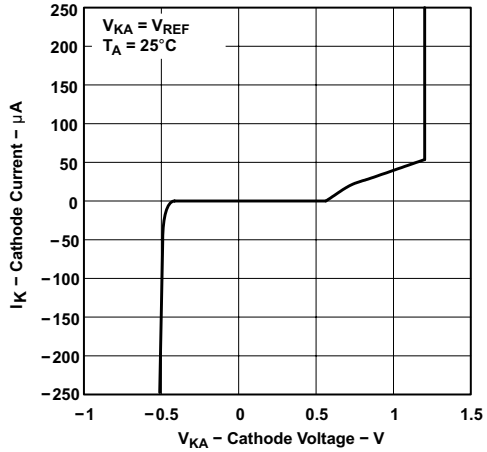


Figure 6. Cathode Current vs Cathode Voltage

Typical Characteristics (continued)

Operation of the device at these or any other conditions beyond those indicated in the *Recommended Operating Conditions* table are not implied.

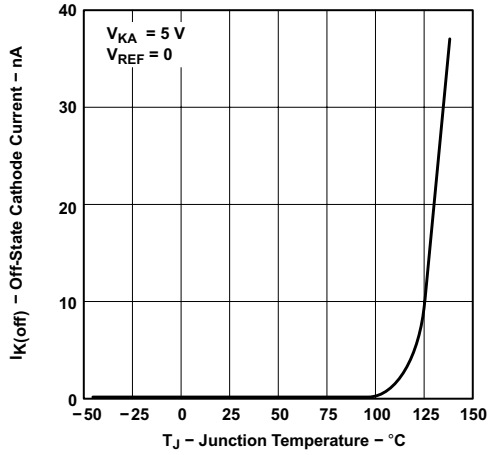


Figure 7. Off-State Cathode Current vs Junction Temperature (for TLV431 and TLV431A)

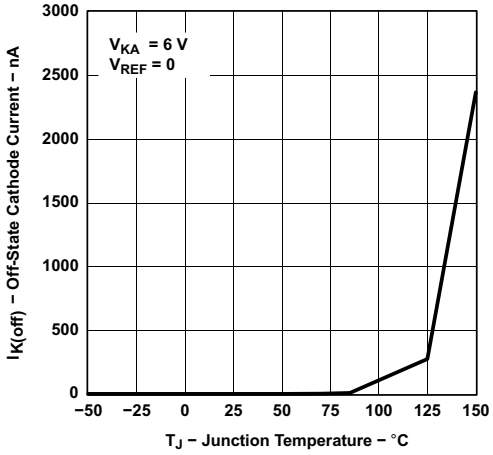


Figure 8. Off-State Cathode Current vs Junction Temperature (for TLV431B)

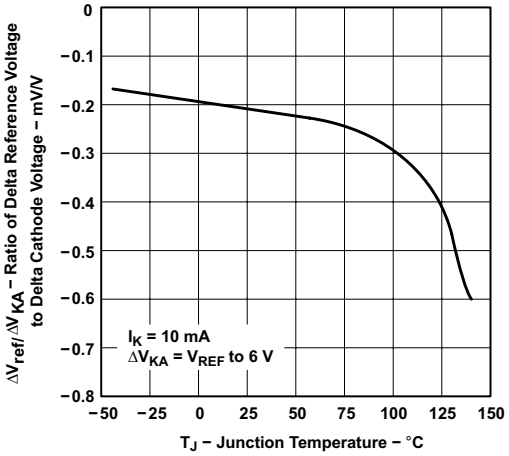


Figure 9. Ratio of Delta Reference Voltage to Delta Cathode Voltage vs Junction Temperature (for TLV431 and TLV431A)

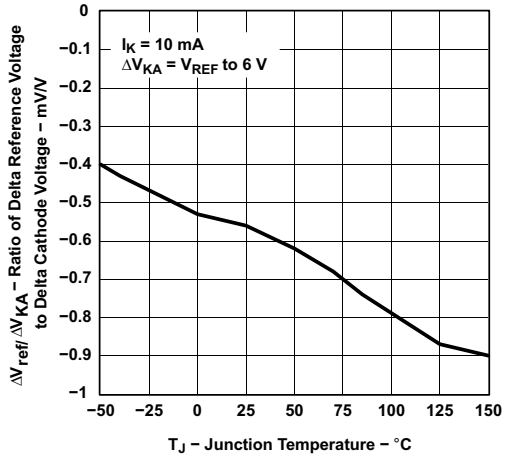
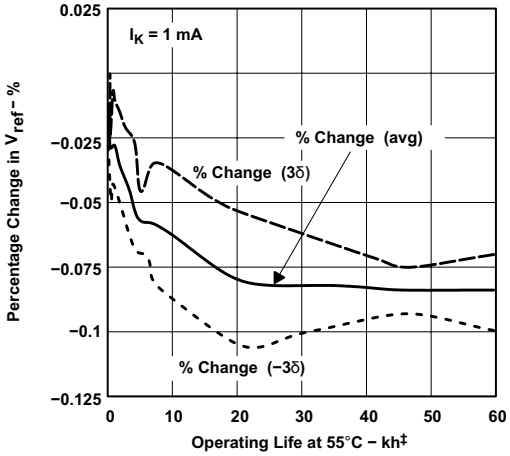


Figure 10. Ratio of Delta Reference Voltage to Delta Cathode Voltage vs Junction Temperature (for TLV431B)

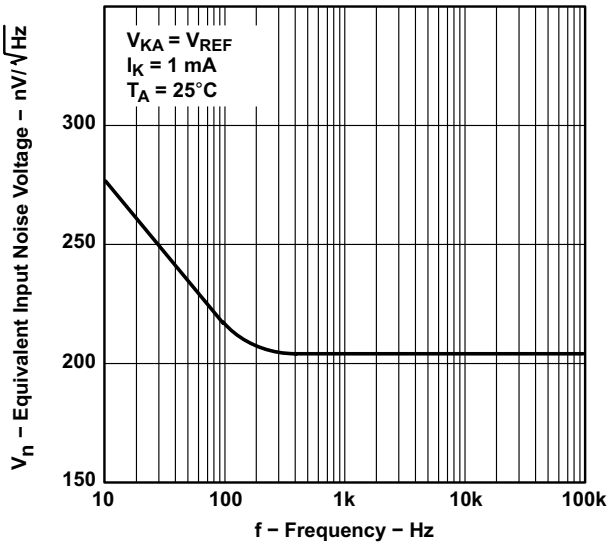
Typical Characteristics (continued)

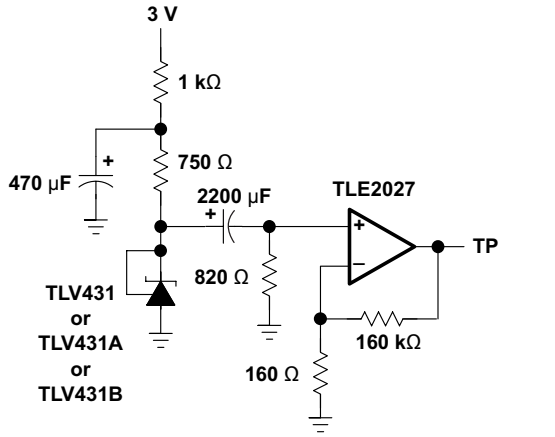
Operation of the device at these or any other conditions beyond those indicated in the *Recommended Operating Conditions* table are not implied.



‡ Extrapolated from life-test data taken at 125°C; the activation energy assumed is 0.7 eV.

Figure 11. Percentage Change in V_{REF} vs Operating Life at 55°C





TEST CIRCUIT FOR EQUIVALENT INPUT NOISE VOLTAGE

Figure 12. Equivalent Input Noise Voltage

Typical Characteristics (continued)

Operation of the device at these or any other conditions beyond those indicated in the *Recommended Operating Conditions* table are not implied.

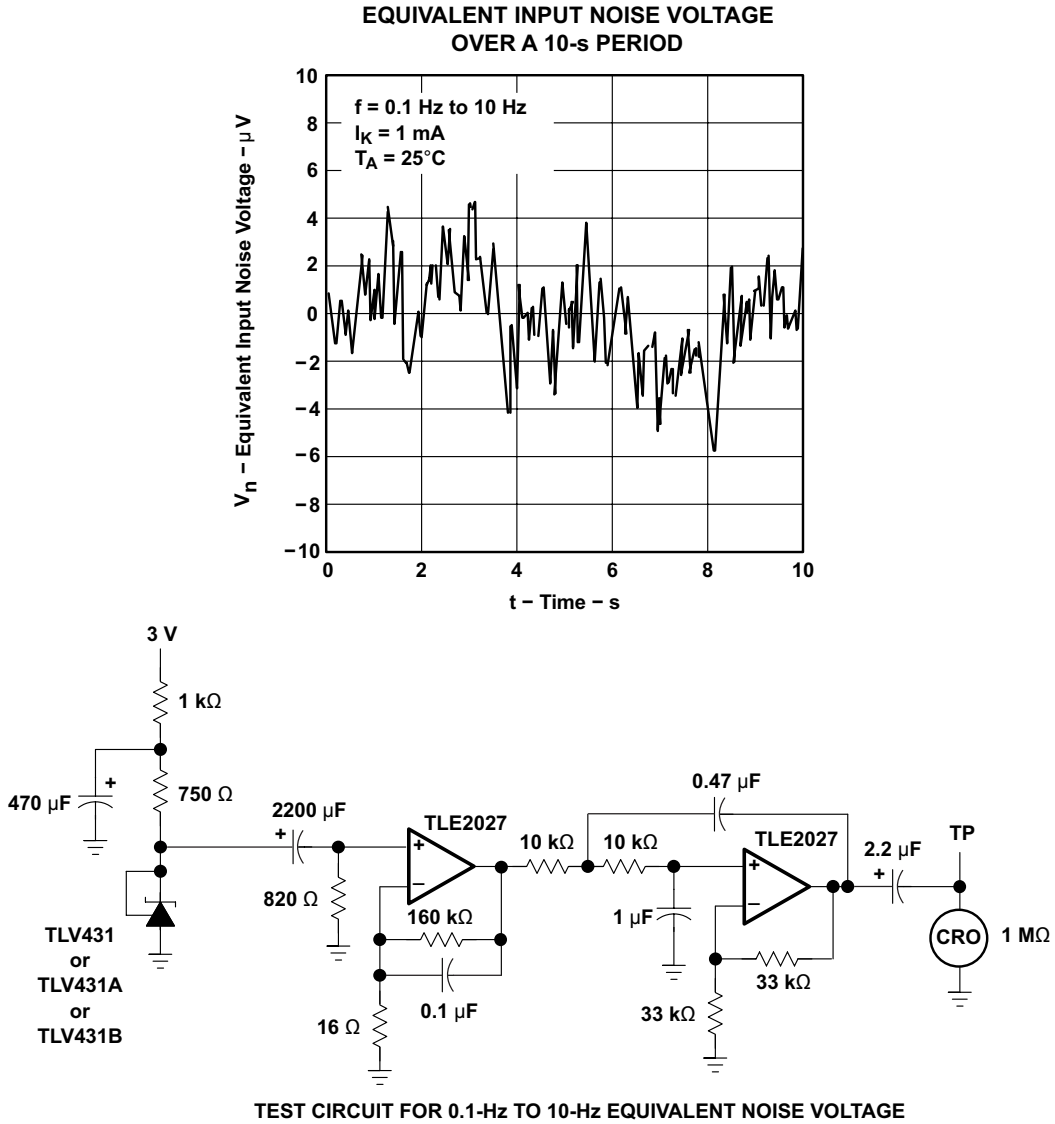


Figure 13. Equivalent Noise Voltage over a 10s Period

Typical Characteristics (continued)

Operation of the device at these or any other conditions beyond those indicated in the *Recommended Operating Conditions* table are not implied.

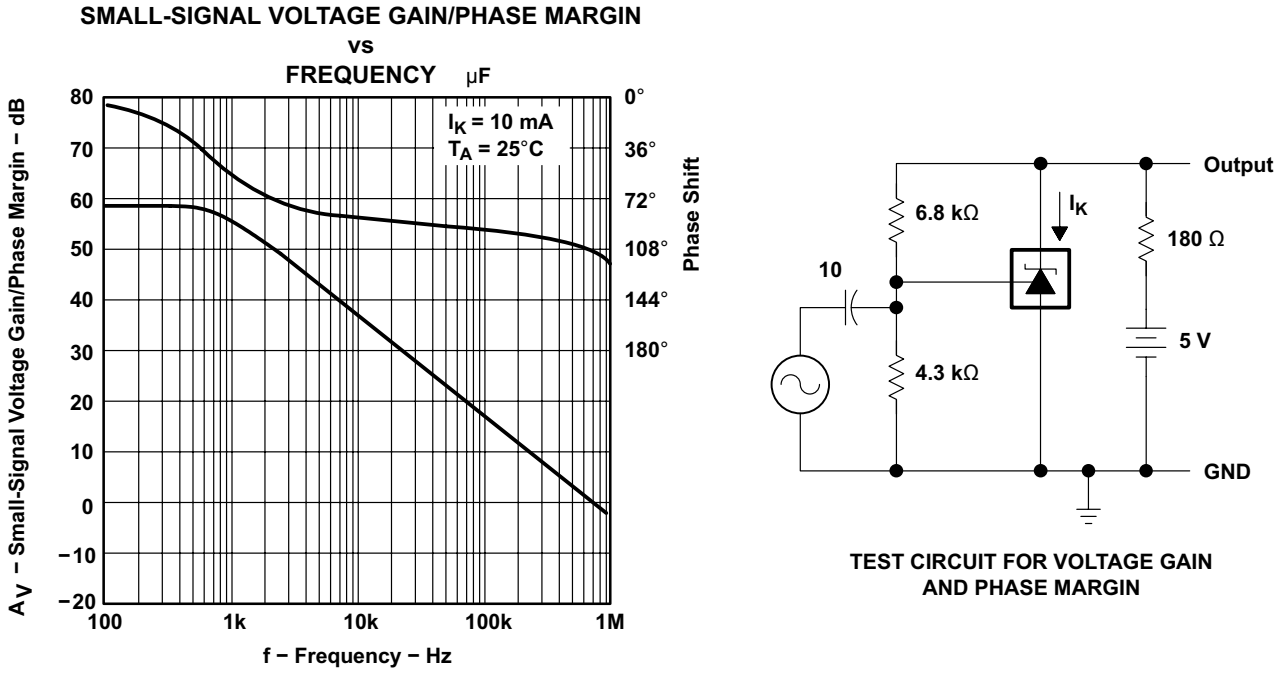


Figure 14. Voltage Gain and Phase Margin

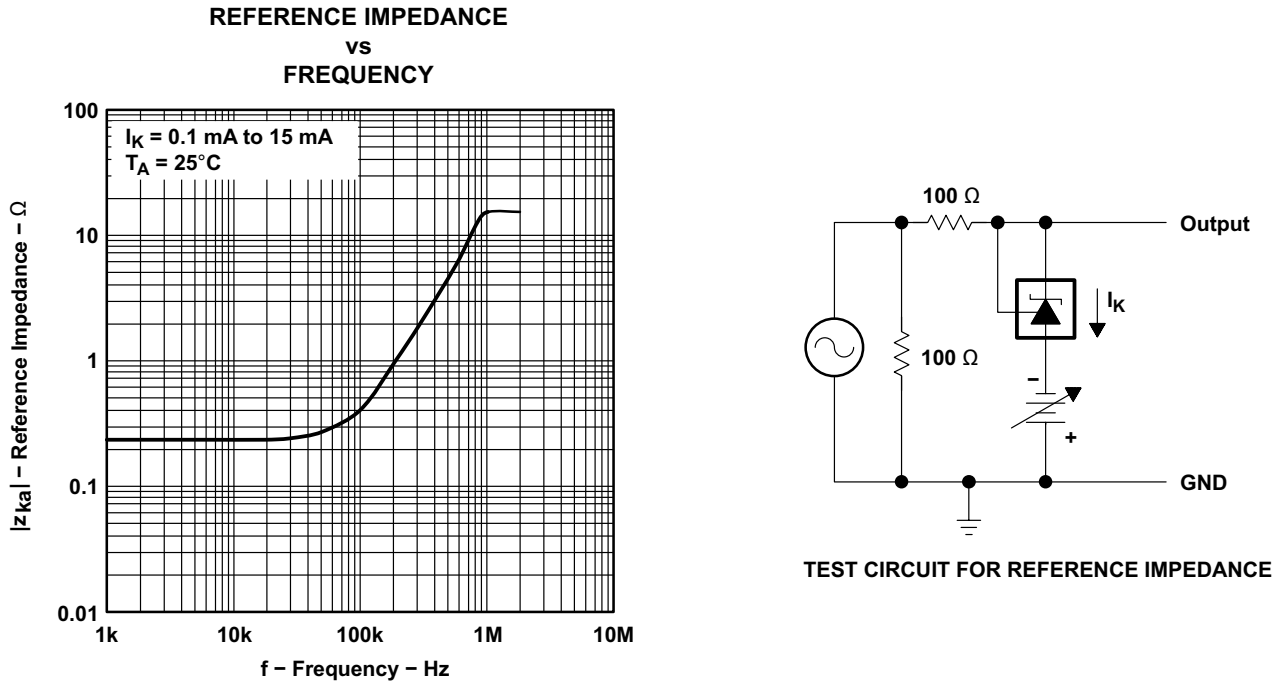


Figure 15. Reference Impedance vs Frequency

Typical Characteristics (continued)

Operation of the device at these or any other conditions beyond those indicated in the *Recommended Operating Conditions* table are not implied.

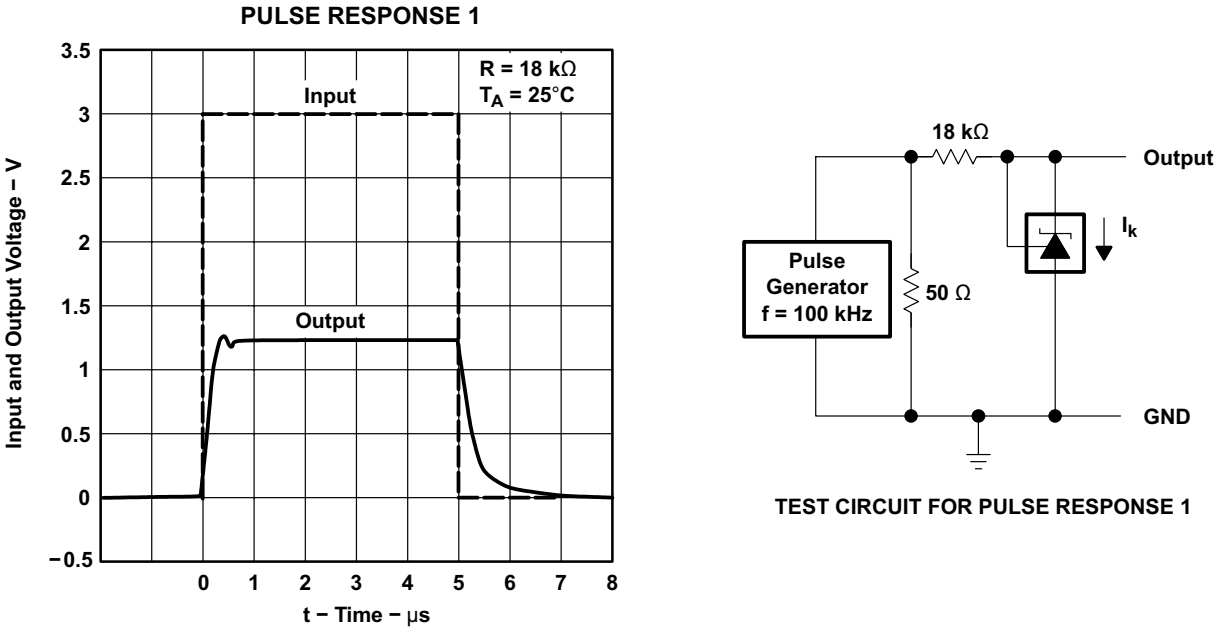


Figure 16. Pulse Response 1

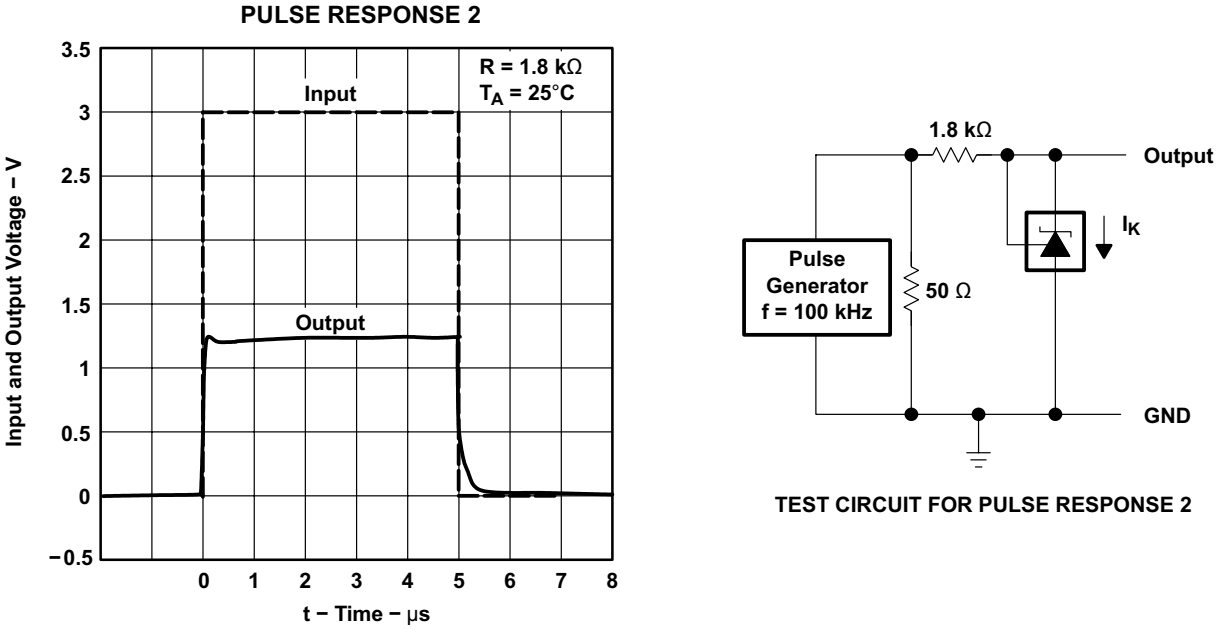
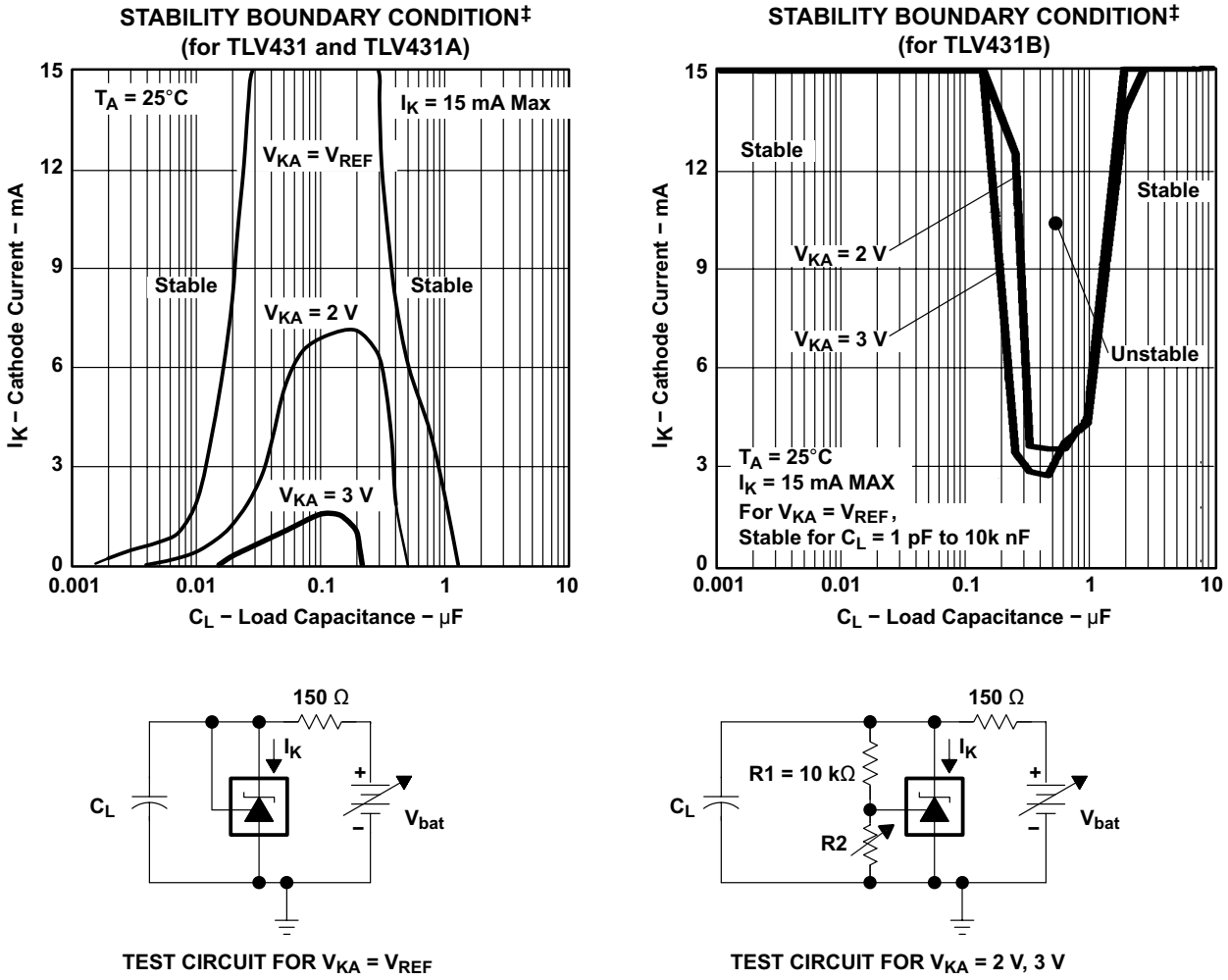


Figure 17. Pulse Response 2

Typical Characteristics (continued)

Operation of the device at these or any other conditions beyond those indicated in the *Recommended Operating Conditions* table are not implied.



‡ The areas under the curves represent conditions that may cause the device to oscillate. For V_{KA} = 2-V and 3-V curves, R2 and V_{bat} were adjusted to establish the initial V_{KA} and I_K conditions with C_L = 0. V_{bat} and C_L then were adjusted to determine the ranges of stability.

Figure 18. Stability Boundary Conditions

8 Parameter Measurement Information

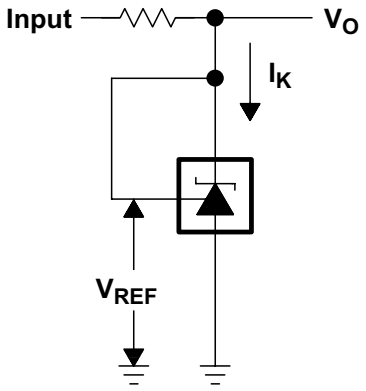


Figure 19. Test Circuit for $V_{KA} = V_{REF}$, $V_O = V_{KA} = V_{REF}$

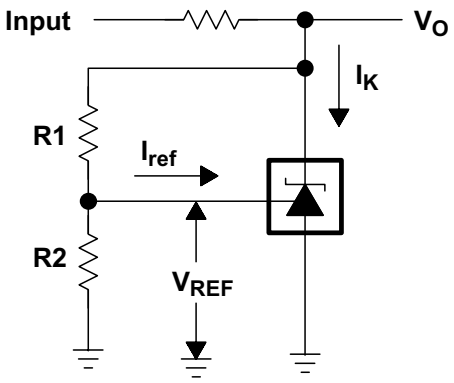


Figure 20. Test Circuit for $V_{KA} > V_{REF}$, $V_O = V_{KA} = V_{REF} \times (1 + R1/R2) + I_{ref} \times R1$

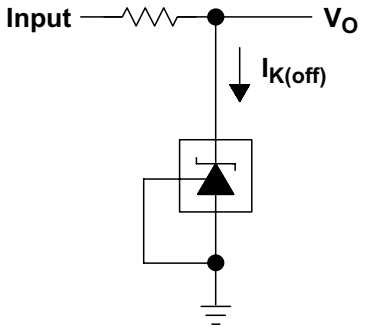


Figure 21. Test Circuit for $I_{K(off)}$

9 Detailed Description

9.1 Overview

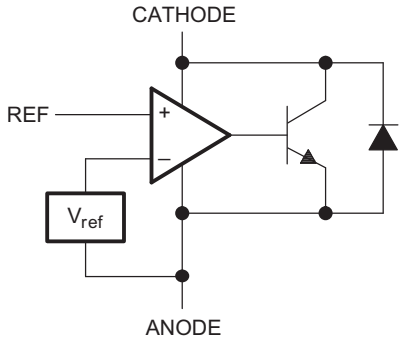
TLV431 is a low power counterpart to TL431, having lower reference voltage (1.24 V vs 2.5 V) for lower voltage adjustability and lower minimum cathode current ($I_{k(min)}$=100 µA vs 1 mA). Like TL431, TLV431 is used in conjunction with it's key components to behave as a single voltage reference, error amplifier, voltage clamp or comparator with integrated reference.

TLV431 can be operated and adjusted to cathode voltages from 1.24V to 6V, making this part optimum for a wide range of end equipments in industrial, auto, telecom & computing. In order for this device to behave as a shunt regulator or error amplifier, > 100 µA (I_{min}(max)) must be supplied in to the cathode pin. Under this condition, feedback can be applied from the Cathode and Ref pins to create a replica of the internal reference voltage.

Various reference voltage options can be purchased with initial tolerances (at 25°C) of 0.5%, 1%, and 1.5%. These reference options are denoted by B (0.5%), A (1.0%) and blank (1.5%) after the TLV431.

The TLV431xC devices are characterized for operation from 0°C to 70°C, the TLV431xI devices are characterized for operation from –40°C to 85°C, and the TLV431xQ devices are characterized for operation from –40°C to 125°C.

9.2 Functional Block Diagram



9.3 Feature Description

TLV431 consists of an internal reference and amplifier that outputs a sink current base on the difference between the reference pin and the virtual internal pin. The sink current is produced by an internal darlington pair.

When operated with enough voltage headroom (≥ 1.24 V) and cathode current (Ika), TLV431 forces the reference pin to 1.24 V. However, the reference pin can not be left floating, as it needs I_{ref} ≥ 0.5 µA (please see the Functional Block Diagram). This is because the reference pin is driven into an npn, which needs base current in order operate properly.

When feedback is applied from the Cathode and Reference pins, TLV431 behaves as a Zener diode, regulating to a constant voltage dependent on current being supplied into the cathode. This is due to the internal amplifier and reference entering the proper operating regions. The same amount of current needed in the above feedback situation must be applied to this device in open loop, servo or error amplifying implementations in order for it to be in the proper linear region giving TLV431 enough gain.

Unlike many linear regulators, TLV431 is internally compensated to be stable without an output capacitor between the cathode and anode. However, if it is desired to use an output capacitor Figure 18 can be used as a guide to assist in choosing the correct capacitor to maintain stability.

9.4 Device Functional Modes

9.4.1 Open Loop (Comparator)

When the cathode/output voltage or current of TLV431 is not being fed back to the reference/input pin in any form, this device is operating in open loop. With proper cathode current (Ika) applied to this device, TLV431 will have the characteristics shown in Figure 6. With such high gain in this configuration, TLV431 is typically used as a comparator. With the reference integrated makes TLV431 the preferred choice when users are trying to monitor a certain level of a single signal.

9.4.2 Closed Loop

When the cathode/output voltage or current of TLV431 is being fed back to the reference/input pin in any form, this device is operating in closed loop. The majority of applications involving TLV431 use it in this manner to regulate a fixed voltage or current. The feedback enables this device to behave as an error amplifier, computing a portion of the output voltage and adjusting it to maintain the desired regulation. This is done by relating the output voltage back to the reference pin in a manner to make it equal to the internal reference voltage, which can be accomplished via resistive or direct feedback.

10 Applications and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

10.1 Application Information

Figure 22 shows the TLV431, TLV431A, or TLV431B used in a 3.3-V isolated flyback supply. Output voltage V_O can be as low as reference voltage V_{REF} (1.24 V ± 1%). The output of the regulator, plus the forward voltage drop of the optocoupler LED (1.24 + 1.4 = 2.64 V), determine the minimum voltage that can be regulated in an isolated supply configuration. Regulated voltage as low as 2.7 Vdc is possible in the topology shown in Figure 22.

The 431 family of devices are prevalent in these applications, being designers go to choice for secondary side regulation. Due to this prevalence, this section will further go on to explain operation and design in both states of TLV431 that this application will see, open loop (Comparator + Vref) & closed loop (Shunt Regulator).

Further information about system stability and using a TLV431 device for compensation can be found in the application note *Compensation Design With TL431 for UCC28600,* SLUA671.

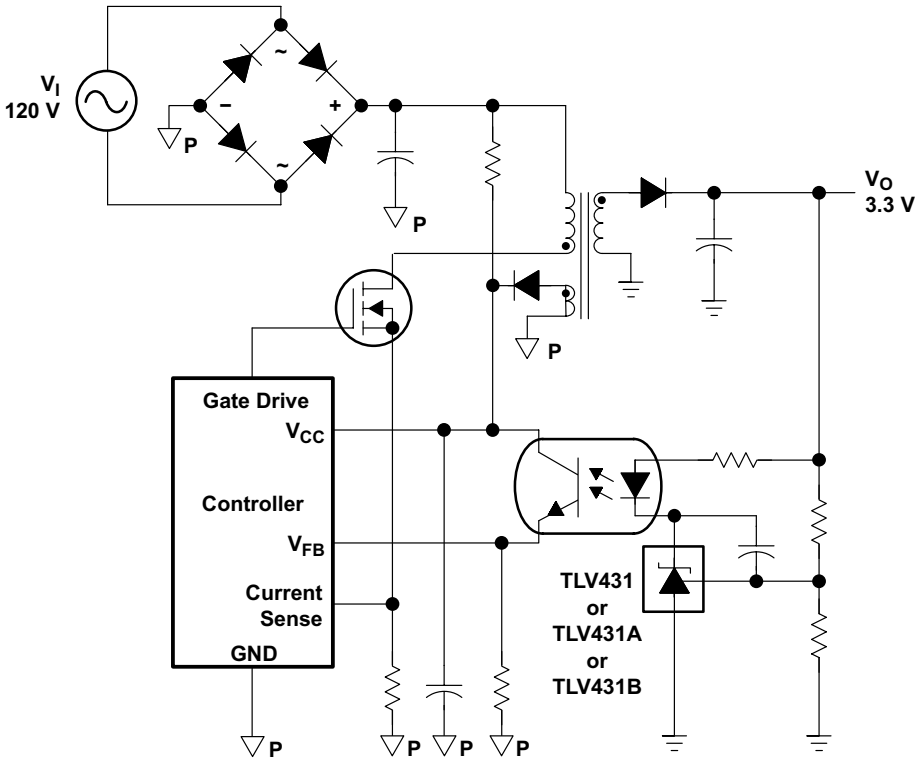


Figure 22. Flyback With Isolation Using TLV431, TLV431A, or TLV431B as Voltage Reference and Error Amplifier

10.2 Typical Applications

10.2.1 Comparator with Integrated Reference (Open Loop)

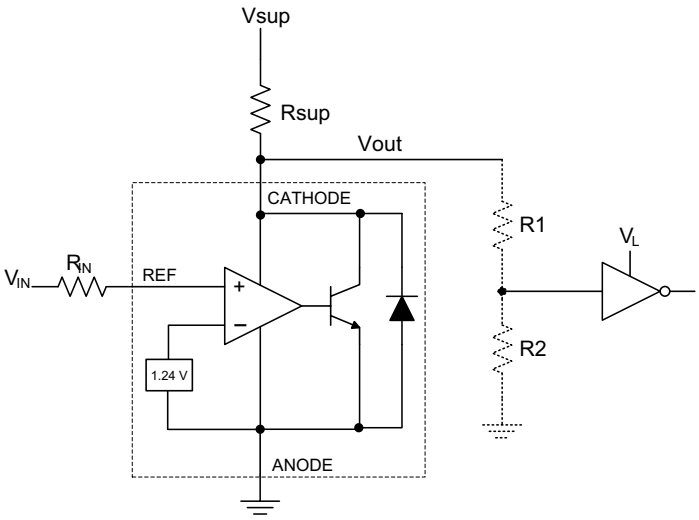


Figure 23. Comparator Application Schematic

10.2.1.1 Design Requirements

For this design example, use the parameters listed in Table 1 as the input parameters.

Table 1. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
Input Voltage Range	0 V to 5 V
Input Resistance	10 kΩ
Supply Voltage	5 V
Cathode Current (Ik)	500 µA
Output Voltage Level	~1 V - Vsup
Logic Input Thresholds VIH/VIL	VL

10.2.1.2 Detailed Design Procedure

When using TLV431 as a comparator with reference, determine the following:

- Input voltage range
- Reference voltage accuracy
- Output logic input high and low level thresholds
- Current source resistance

10.2.1.2.1 Basic Operation

In the configuration shown in Figure 23 TLV431 will behave as a comparator, comparing the V_{ref} pin voltage to the internal virtual reference voltage. When provided a proper cathode current (I_k), TLV431 will have enough open loop gain to provide a quick response. With the TLV431's max Operating Current (Imin) being 100 uA and up to 150 uA over temperature, operation below that could result in low gain, leading to a slow response.

10.2.1.2.2 Overdrive

Slow or inaccurate responses can also occur when the reference pin is not provided enough overdrive voltage. This is the amount of voltage that is higher than the internal virtual reference. The internal virtual reference voltage will be within the range of 1.24V ±(0.5%, 1.0% or 1.5%) depending on which version is being used.

The more overdrive voltage provided, the faster the TLV431 will respond. This can be seen in figures Figure 24 and Figure 25, where it displays the output responses to various input voltages.

For applications where TLV431 is being used as a comparator, it is best to set the trip point to greater than the positive expected error (i.e. +1.0% for the A version). For fast response, setting the trip point to > 10% of the internal V_{ref} should suffice.

For minimal voltage drop or difference from Vin to the ref pin, it is recommended to use an input resistor < 10 kΩ to provide I_{ref}.

10.2.1.2.3 Output Voltage and Logic Input Level

In order for TLV431 to properly be used as a comparator, the logic output must be readable by the recieving logic device. This is accomplished by knowing the input high and low level threshold voltage levels, typically denoted by V_{IH} & V_{IL}.

As seen in Figure 24, TLV431's output low level voltage in open-loop/comparator mode is ~1 V, which is sufficient for some 3.3V supplied logic. However, would not work for 2.5 V and 1.8 V supplied logic. In order to accommodate this a resistive divider can be tied to the output to attenuate the output voltage to a voltage legible to the receiving low voltage logic device.

TLV431's output high voltage is approximately V_{sup} due to TLV431 being open-collector. If V_{sup} is much higher than the receiving logic's maximum input voltage tolerance, the output must be attenuated to accommodate the outgoing logic's reliability.

When using a resistive divider on the output, be sure to make the sum of the resistive divider (R1 & R2 in Figure 23) is much greater than R_{sup} in order to not interfere with TLV431's ability to pull close to V_{sup} when turning off.

10.2.1.2.3.1 Input Resistance

TLV431 requires an input resistance in this application in order to source the reference current (I_{ref}) needed from this device to be in the proper operating regions while turning on. The actual voltage seen at the ref pin will be $V_{ref}=V_{in}-I_{ref}*R_{in}$. Since I_{ref} can be as high as 0.5 µA it is recommended to use a resistance small enough that will mitigate the error that I_{ref} creates from V_{in}.

10.2.1.3 Application Curves

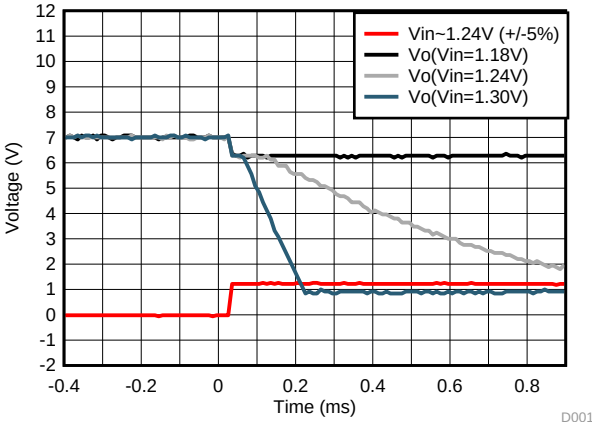


Figure 24. Output Response with Small Overdrive Voltages

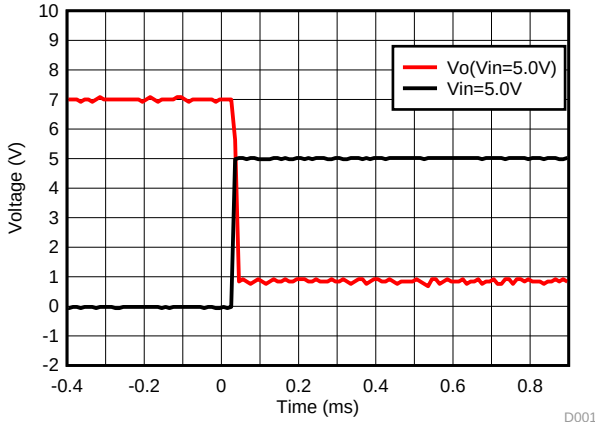


Figure 25. Output Response with Large Overdrive Voltage

10.2.2 Shunt Regulator/Reference

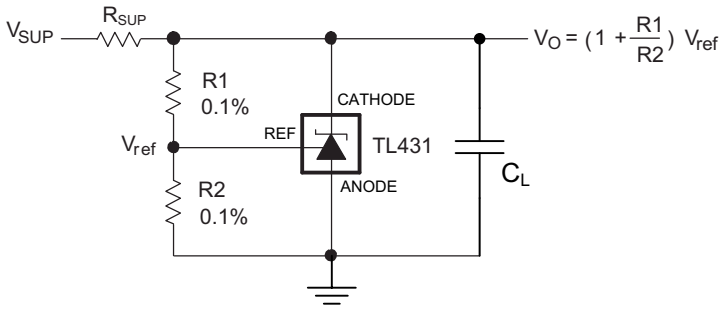


Figure 26. Shunt Regulator Schematic

10.2.2.1 Design Requirements

For this design example, use the parameters listed in Table 2 as the input parameters.

Table 2. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
Reference Initial Accuracy	1.0%
Supply Voltage	6 V
Cathode Current (Ik)	1 mA
Output Voltage Level	1.24 V - 6 V
Load Capacitance	100 nF
Feedback Resistor Values and Accuracy (R1 & R2)	10 kΩ

10.2.2.2 Detailed Design Procedure

When using TLV431 as a Shunt Regulator, determine the following:

- Input voltage range
- Temperature range
- Total accuracy
- Cathode current
- Reference initial accuracy
- Output capacitance

10.2.2.2.1 Programming Output/Cathode Voltage

In order to program the cathode voltage to a regulated voltage a resistive bridge must be shunted between the cathode and anode pins with the mid point tied to the reference pin. This can be seen in Figure 26, with R1 & R2 being the resistive bridge. The cathode/output voltage in the shunt regulator configuration can be approximated by the equation shown in Figure 26. The cathode voltage can be more accuratel determined by taking in to account the cathode current:

$V_O=(1+R1/R2)*V_{ref}–I_{ref}*R1$

In order for this equation to be valid, TLV431 must be fully biased so that it has enough open loop gain to mitigate any gain error. This can be done by meeting the I_{min} spec denoted in *Recommended Operating Conditions* table.

10.2.2.2.2 Total Accuracy

When programming the output above unity gain (Vka=Vref), TLV431 is susceptible to other errors that may effect the overall accuracy beyond V_{ref}. These errors include:

- R1 and R2 accuracies
- $V_{I(dev)}$ - Change in reference voltage over temperature
- ΔV_{ref} / ΔV_{KA} - Change in reference voltage to the change in cathode voltage
- $|z_{KA}|$ - Dynamic impedance, causing a change in cathode voltage with cathode current

Worst case cathode voltage can be determined taking all of the variables in to account. Application note SLVA445 assists designers in setting the shunt voltage to achieve optimum accuracy for this device.

10.2.2.2.3 Stability

Though TLV431 is stable with no capacitive load, the device that receives the shunt regulator's output voltage could present a capacitive load that is within the TLV431 region of stability, shown in Figure 18. Also, designers may use capacitive loads to improve the transient response or for power supply decoupling.

10.2.2.3 Application Curves

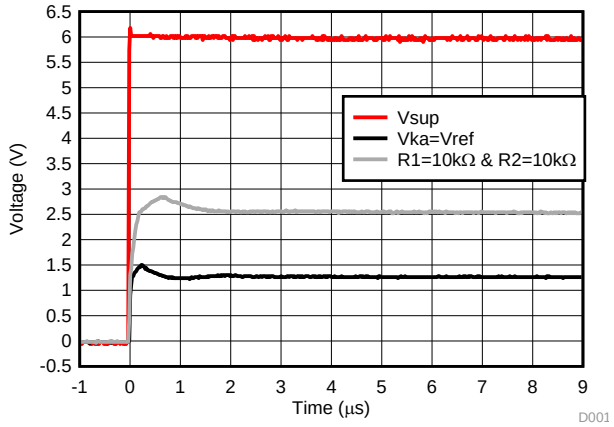


Figure 27. TLV431 Start-up Response

11 Power Supply Recommendations

When using TLV431 as a Linear Regulator to supply a load, designers will typically use a bypass capacitor on the output/cathode pin. When doing this, be sure that the capacitance is within the stability criteria shown in Figure 18.

In order to not exceed the maximum cathode current, be sure that the supply voltage is current limited. Also, be sure to limit the current being driven into the Ref pin, as not to exceed it's absolute maximum rating.

For applications shunting high currents, pay attention to the cathode and anode trace lengths, adjusting the width of the traces to have the proper current density.

12 Layout

12.1 Layout Guidelines

Place decoupling capacitors as close to the device as possible. Use appropriate widths for traces when shunting high currents to avoid excessive voltage drops.

12.2 Layout Example

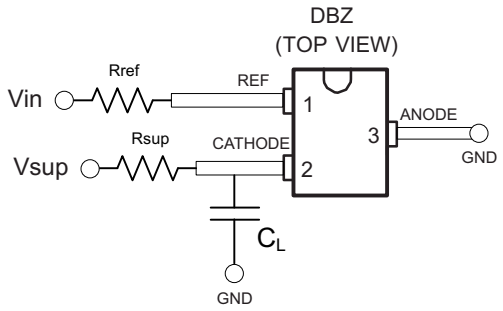


Figure 28. DBZ Layout Example

13 Device and Documentation Support

13.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 3. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
TLV431	Click here	Click here	Click here	Click here	Click here
TLV431A	Click here	Click here	Click here	Click here	Click here
TLV431B	Click here	Click here	Click here	Click here	Click here

13.2 Trademarks

All trademarks are the property of their respective owners.

13.3 Electrostatic Discharge Caution

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

13.4 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser based versions of this data sheet, refer to the left hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLV431ACDBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	(YAC6 ~ YACC ~ YACI ~ YACN) (YACG ~ YACL ~ YACS)	Samples
TLV431ACDBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	YACI	Samples
TLV431ACDBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	YACI	Samples
TLV431ACDBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	(YAC6 ~ YACC ~ YACI) (YACG ~ YACL ~ YACS)	Samples
TLV431ACDBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	YACI	Samples
TLV431ACDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	(YAC6 ~ YAC8 ~ YACB) (YAC3 ~ YACS ~ YACU)	Samples
TLV431ACDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	(YAC6 ~ YAC8 ~ YACB) (YAC3 ~ YACS ~ YACU)	Samples
TLV431ACLP	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	V431AC	Samples
TLV431ACLPE3	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	V431AC	Samples
TLV431ACLPR	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	V431AC	Samples
TLV431ACLPRE3	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	V431AC	Samples
TLV431AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TY431A	Samples
TLV431AIDBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	-40 to 85	(YAI6 ~ YAIC ~ YAII ~ YAIN) (YAIG ~ YAIL ~ YAIS)	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLV431AIDBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	YAII	Samples
TLV431AIDBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	YAII	Samples
TLV431AIDBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	-40 to 85	(YAI6 ~ YAIC ~ YAII) (YAIG ~ YAIL ~ YAIS)	Samples
TLV431AIDBVTE4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	YAII	Samples
TLV431AIDBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	YAII	Samples
TLV431AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(YAI6 ~ YAI8 ~ YAIB) (YAI3 ~ YAIS ~ YAIU)	Samples
TLV431AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(YAI6 ~ YAI8 ~ YAIB) (YAI3 ~ YAIS ~ YAIU)	Samples
TLV431AIDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TY431A	Samples
TLV431AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TY431A	Samples
TLV431AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TY431A	Samples
TLV431AIDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TY431A	Samples
TLV431AIDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TY431A	Samples
TLV431AILP	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 85	V431AI	Samples
TLV431AILPE3	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 85	V431AI	Samples
TLV431AILPM	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 85	V431AI	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLV431AILPME3	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 85	V431AI	Samples
TLV431AILPR	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 85	V431AI	Samples
TLV431AILPRE3	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 85	V431AI	Samples
TLV431AQPK	ACTIVE	SOT-89	PK	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR	-40 to 125	VA	Samples
TLV431AQPKG3	ACTIVE	SOT-89	PK	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR	-40 to 125	VA	Samples
TLV431BCDBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	0 to 70	(Y3GG ~ Y3GU)	Samples
TLV431BCDBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	Y3GG	Samples
TLV431BCDBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	0 to 70	(Y3GG ~ Y3GU)	Samples
TLV431BCDBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	Y3GG	Samples
TLV431BCDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	(Y3G3 ~ Y3GS ~ Y3GU)	Samples
TLV431BCDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	(Y3G3 ~ Y3GS ~ Y3GU)	Samples
TLV431BCDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	(Y3GS ~ Y3GU)	Samples
TLV431BCDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	(Y3GS ~ Y3GU)	Samples
TLV431BCDCKR	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	YEU	Samples
TLV431BCDCKT	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	YEU	Samples
TLV431BCLP	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	TV431B	Samples
TLV431BCLPR	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	TV431B	Samples
TLV431BCLPRE3	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	TV431B	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLV431BCPK	ACTIVE	SOT-89	PK	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR	0 to 70	VE	Samples
TLV431BIDBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	Y3FU	Samples
TLV431BIDBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	Y3FU	Samples
TLV431BIDBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	Y3FU	Samples
TLV431BIDBVTE4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	Y3FU	Samples
TLV431BIDBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	Y3FU	Samples
TLV431BIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(Y3F3 ~ Y3FS ~ Y3FU)	Samples
TLV431BIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(Y3F3 ~ Y3FS ~ Y3FU)	Samples
TLV431BIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(Y3FS ~ Y3FU)	Samples
TLV431BIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(Y3FS ~ Y3FU)	Samples
TLV431BIDCKR	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	YFU	Samples
TLV431BIDCKRE4	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	YFU	Samples
TLV431BIDCKRG4	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	YFU	Samples
TLV431BIDCKT	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	YFU	Samples
TLV431BIDCKTE4	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	YFU	Samples
TLV431BIDCKTG4	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	YFU	Samples
TLV431BILP	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 85	TY431B	Samples
TLV431BILPR	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 85	TY431B	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLV431BILPRE3	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 85	TY431B	Samples
TLV431BIPK	ACTIVE	SOT-89	PK	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR	-40 to 85	VF	Samples
TLV431BIPKG3	ACTIVE	SOT-89	PK	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR	-40 to 85	VF	Samples
TLV431BQDBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	Y3HU	Samples
TLV431BQDBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	Y3HU	Samples
TLV431BQDBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	Y3HU	Samples
TLV431BQDBVTE4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	Y3HU	Samples
TLV431BQDBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	Y3HU	Samples
TLV431BQDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(Y3H3 ~ Y3HS ~ Y3HU)	Samples
TLV431BQDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(Y3H3 ~ Y3HS ~ Y3HU)	Samples
TLV431BQDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(Y3HS ~ Y3HU)	Samples
TLV431BQDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(Y3HS ~ Y3HU)	Samples
TLV431BQDCKR	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	YGU	Samples
TLV431BQDCKT	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	YGU	Samples
TLV431BQLP	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 125	TQ431B	Samples
TLV431BQLPR	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 125	TQ431B	Samples
TLV431BQPK	ACTIVE	SOT-89	PK	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR	-40 to 125	V6	Samples
TLV431BQPKG3	ACTIVE	SOT-89	PK	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR	-40 to 125	V6	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLV431CDBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	0 to 70	(Y3C6 ~ Y3CI) (Y3CG ~ Y3CS)	Samples
TLV431CDBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	Y3CI	Samples
TLV431CDBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	Y3CI	Samples
TLV431CDBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	0 to 70	(Y3C6 ~ Y3CI) (Y3CG ~ Y3CS)	Samples
TLV431CDBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	Y3CI	Samples
TLV431CDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	(Y3C6 ~ Y3C8 ~ Y3CB) (Y3C3 ~ Y3CS ~ Y3CU)	Samples
TLV431CDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	(Y3C6 ~ Y3C8 ~ Y3CB) (Y3C3 ~ Y3CS ~ Y3CU)	Samples
TLV431CLP	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	V431C	Samples
TLV431CLPE3	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	V431C	Samples
TLV431CLPM	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	V431C	Samples
TLV431CLPME3	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	V431C	Samples
TLV431CLPR	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	V431C	Samples
TLV431CLPRE3	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	V431C	Samples
TLV431IDBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	-40 to 85	(Y3I6 ~ Y3II) (Y3IG ~ Y3IS)	Samples
TLV431IDBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	Y3II	Samples
TLV431IDBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	-40 to 85	(Y3I6 ~ Y3II) (Y3IG ~ Y3IS)	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLV431IDBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	Y3II	Samples
TLV431IDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(Y3I6 ~ Y3IB) (Y3IS ~ Y3IU)	Samples
TLV431IDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(Y3I6 ~ Y3IB) (Y3IS ~ Y3IU)	Samples
TLV431ILP	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 85	V431I	Samples
TLV431ILPE3	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 85	V431I	Samples
TLV431ILPR	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 85	V431I	Samples
TLV431QPK	ACTIVE	SOT-89	PK	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR	-40 to 125	VB	Samples
TLV431QPKG3	ACTIVE	SOT-89	PK	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR	-40 to 125	VB	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

OTHER QUALIFIED VERSIONS OF TLV431A, TLV431B :

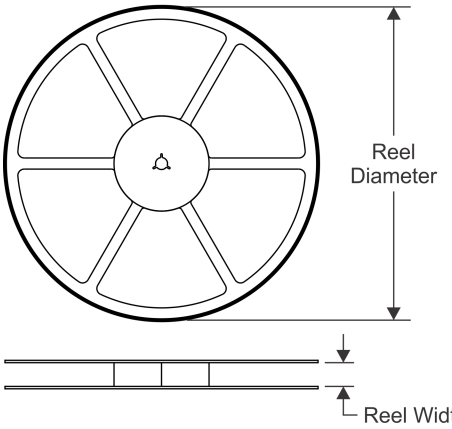
- Automotive: TLV431A-Q1, TLV431B-Q1

NOTE: Qualified Version Definitions:

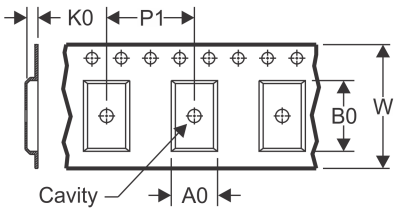
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

REEL DIMENSIONS

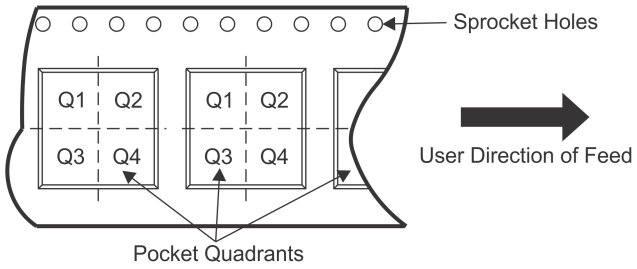


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

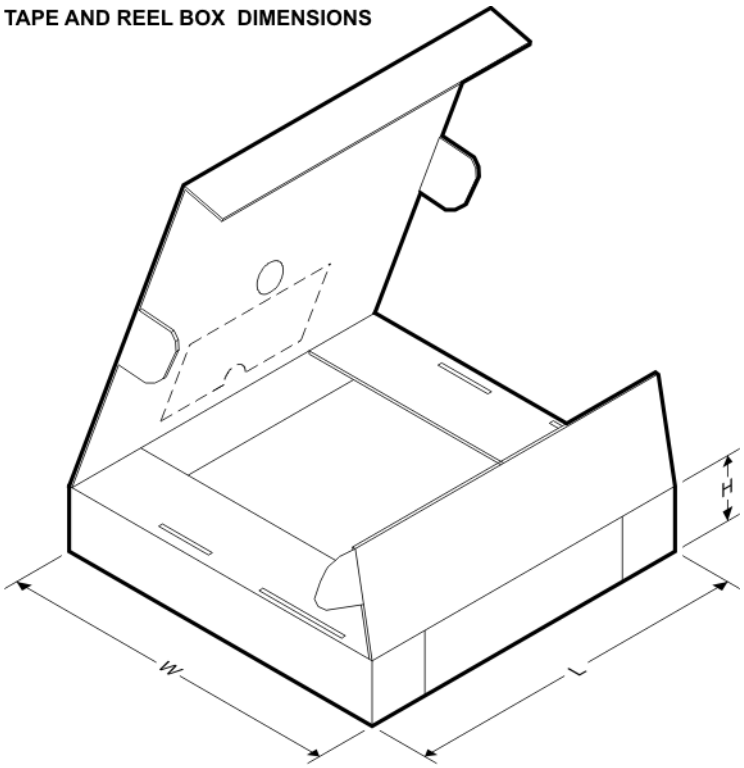


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLV431ACDBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TLV431ACDBVR	SOT-23	DBV	5	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
TLV431ACDBVRG4	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TLV431ACDBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TLV431ACDBVTG4	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TLV431ACDBZR	SOT-23	DBZ	3	3000	180.0	8.4	3.15	2.77	1.22	4.0	8.0	Q3
TLV431AIDBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TLV431AIDBVRG4	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TLV431AIDBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TLV431AIDBVTG4	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TLV431AIDBZR	SOT-23	DBZ	3	3000	180.0	8.4	3.15	2.77	1.22	4.0	8.0	Q3
TLV431AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLV431AQPK	SOT-89	PK	3	1000	180.0	12.4	4.91	4.52	1.9	8.0	12.0	Q3
TLV431BCDBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TLV431BCDBVRG4	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TLV431BCDBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TLV431BCDBVTG4	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TLV431BCDBZR	SOT-23	DBZ	3	3000	180.0	8.4	3.15	2.77	1.22	4.0	8.0	Q3

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLV431BCDBZT	SOT-23	DBZ	3	250	180.0	8.4	3.15	2.77	1.22	4.0	8.0	Q3
TLV431BCDCKR	SC70	DCK	6	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TLV431BCDCKT	SC70	DCK	6	250	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TLV431BCPK	SOT-89	PK	3	1000	180.0	12.4	4.91	4.52	1.9	8.0	12.0	Q3
TLV431BIDBVR	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TLV431BIDBVT	SOT-23	DBV	5	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TLV431BIDBZR	SOT-23	DBZ	3	3000	180.0	8.4	3.15	2.77	1.22	4.0	8.0	Q3
TLV431BIDBZT	SOT-23	DBZ	3	250	180.0	8.4	3.15	2.77	1.22	4.0	8.0	Q3
TLV431BIDCKR	SC70	DCK	6	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TLV431BIDCKT	SC70	DCK	6	250	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TLV431BIPK	SOT-89	PK	3	1000	180.0	12.4	4.91	4.52	1.9	8.0	12.0	Q3
TLV431BQDBVR	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TLV431BQDBVT	SOT-23	DBV	5	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TLV431BQDBZR	SOT-23	DBZ	3	3000	180.0	8.4	3.15	2.77	1.22	4.0	8.0	Q3
TLV431BQDBZT	SOT-23	DBZ	3	250	180.0	8.4	3.15	2.77	1.22	4.0	8.0	Q3
TLV431BQDCKR	SC70	DCK	6	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TLV431BQDCKT	SC70	DCK	6	250	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TLV431BQPK	SOT-89	PK	3	1000	180.0	12.4	4.91	4.52	1.9	8.0	12.0	Q3
TLV431CDBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TLV431CDBVR	SOT-23	DBV	5	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
TLV431CDBVRG4	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TLV431CDBVT	SOT-23	DBV	5	250	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
TLV431CDBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TLV431CDBVTG4	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TLV431CDBZR	SOT-23	DBZ	3	3000	180.0	8.4	3.15	2.77	1.22	4.0	8.0	Q3
TLV431IDBVR	SOT-23	DBV	5	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TLV431IDBVRG4	SOT-23	DBV	5	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TLV431IDBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TLV431IDBVTG4	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TLV431IDBZR	SOT-23	DBZ	3	3000	180.0	8.4	3.15	2.77	1.22	4.0	8.0	Q3
TLV431QPK	SOT-89	PK	3	1000	180.0	12.4	4.91	4.52	1.9	8.0	12.0	Q3

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

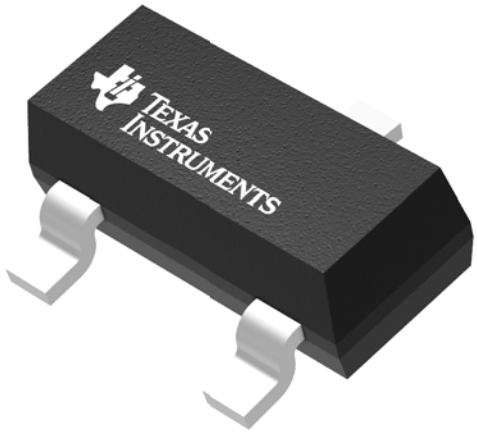
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLV431ACDBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TLV431ACDBVR	SOT-23	DBV	5	3000	202.0	201.0	28.0
TLV431ACDBVRG4	SOT-23	DBV	5	3000	180.0	180.0	18.0
TLV431ACDBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TLV431ACDBVTG4	SOT-23	DBV	5	250	180.0	180.0	18.0
TLV431ACDBZR	SOT-23	DBZ	3	3000	202.0	201.0	28.0
TLV431AIDBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TLV431AIDBVRG4	SOT-23	DBV	5	3000	180.0	180.0	18.0
TLV431AIDBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TLV431AIDBVTG4	SOT-23	DBV	5	250	180.0	180.0	18.0
TLV431AIDBZR	SOT-23	DBZ	3	3000	202.0	201.0	28.0
TLV431AIDR	SOIC	D	8	2500	340.5	338.1	20.6
TLV431AQPK	SOT-89	PK	3	1000	340.0	340.0	38.0
TLV431BCDBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TLV431BCDBVRG4	SOT-23	DBV	5	3000	180.0	180.0	18.0
TLV431BCDBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TLV431BCDBVTG4	SOT-23	DBV	5	250	180.0	180.0	18.0
TLV431BCDBZR	SOT-23	DBZ	3	3000	202.0	201.0	28.0
TLV431BCDBZT	SOT-23	DBZ	3	250	202.0	201.0	28.0
TLV431BCDCKR	SC70	DCK	6	3000	203.0	203.0	35.0

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLV431BCDCKT	SC70	DCK	6	250	203.0	203.0	35.0
TLV431BCPK	SOT-89	PK	3	1000	340.0	340.0	38.0
TLV431BIDBVR	SOT-23	DBV	5	3000	203.0	203.0	35.0
TLV431BIDBVT	SOT-23	DBV	5	250	203.0	203.0	35.0
TLV431BIDBZR	SOT-23	DBZ	3	3000	202.0	201.0	28.0
TLV431BIDBZT	SOT-23	DBZ	3	250	202.0	201.0	28.0
TLV431BIDCKR	SC70	DCK	6	3000	203.0	203.0	35.0
TLV431BIDCKT	SC70	DCK	6	250	203.0	203.0	35.0
TLV431BIPK	SOT-89	PK	3	1000	340.0	340.0	38.0
TLV431BQDBVR	SOT-23	DBV	5	3000	203.0	203.0	35.0
TLV431BQDBVT	SOT-23	DBV	5	250	203.0	203.0	35.0
TLV431BQDBZR	SOT-23	DBZ	3	3000	202.0	201.0	28.0
TLV431BQDBZT	SOT-23	DBZ	3	250	202.0	201.0	28.0
TLV431BQDCKR	SC70	DCK	6	3000	203.0	203.0	35.0
TLV431BQDCKT	SC70	DCK	6	250	203.0	203.0	35.0
TLV431BQPK	SOT-89	PK	3	1000	340.0	340.0	38.0
TLV431CDBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TLV431CDBVR	SOT-23	DBV	5	3000	202.0	201.0	28.0
TLV431CDBVRG4	SOT-23	DBV	5	3000	180.0	180.0	18.0
TLV431CDBVT	SOT-23	DBV	5	250	202.0	201.0	28.0
TLV431CDBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TLV431CDBVTG4	SOT-23	DBV	5	250	180.0	180.0	18.0
TLV431CDBZR	SOT-23	DBZ	3	3000	202.0	201.0	28.0
TLV431IDBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TLV431IDBVRG4	SOT-23	DBV	5	3000	180.0	180.0	18.0
TLV431IDBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TLV431IDBVTG4	SOT-23	DBV	5	250	180.0	180.0	18.0
TLV431IDBZR	SOT-23	DBZ	3	3000	202.0	201.0	28.0
TLV431QPK	SOT-89	PK	3	1000	340.0	340.0	38.0

GENERIC PACKAGE VIEW

DBZ 3 SOT-23 - 1.12 mm max height

SMALL OUTLINE TRANSISTOR



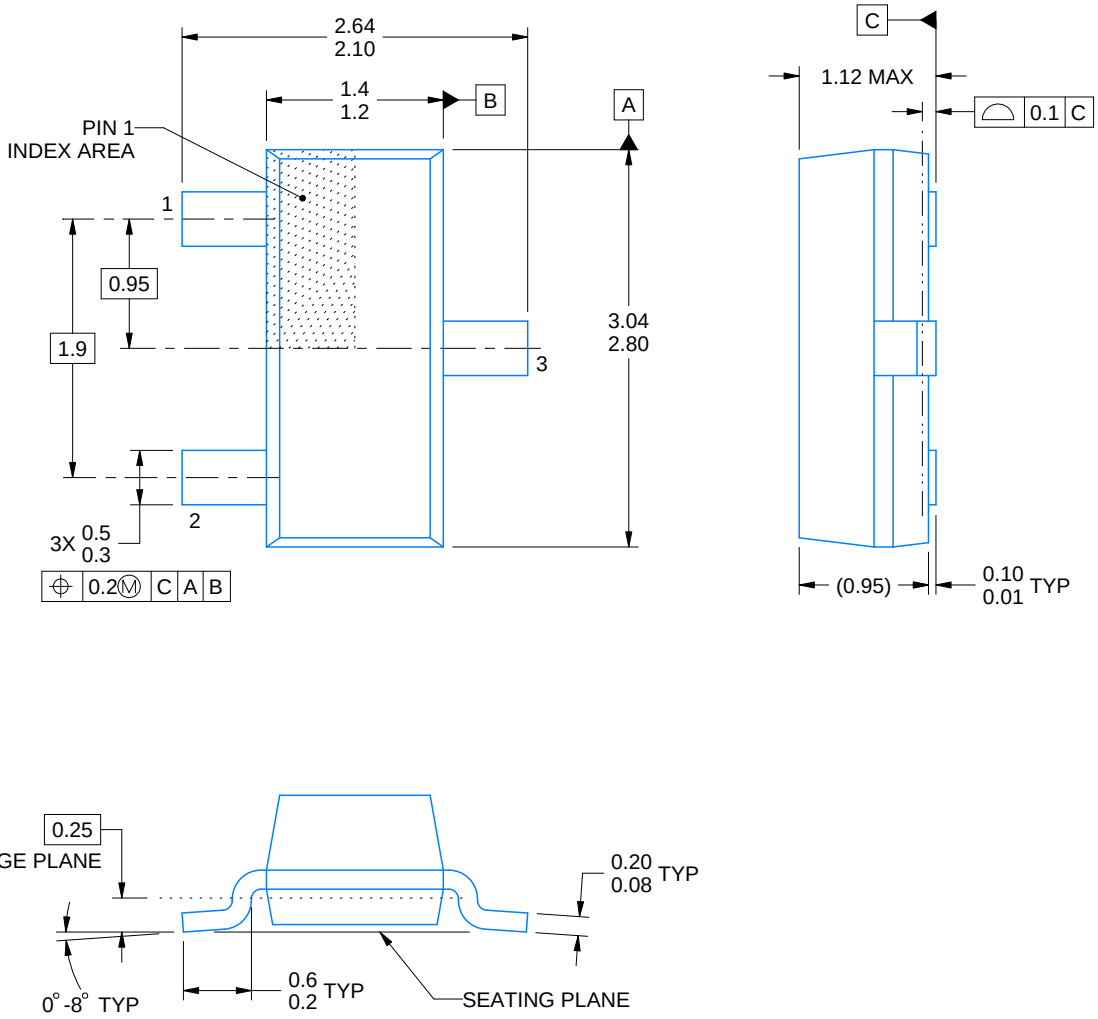
Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

PACKAGE OUTLINE

DBZ0003A

SOT-23 - 1.12 mm max height

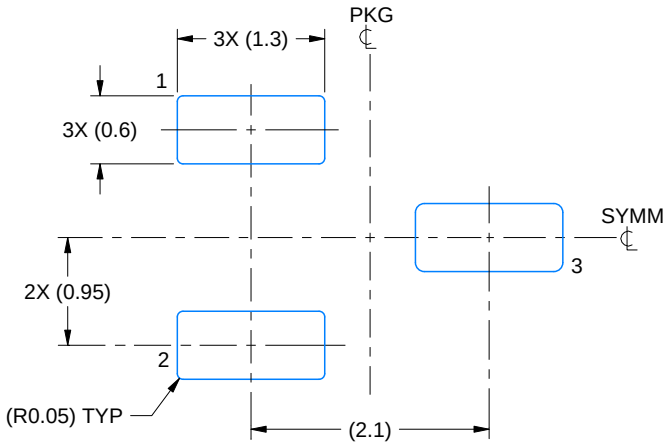
SMALL OUTLINE TRANSISTOR



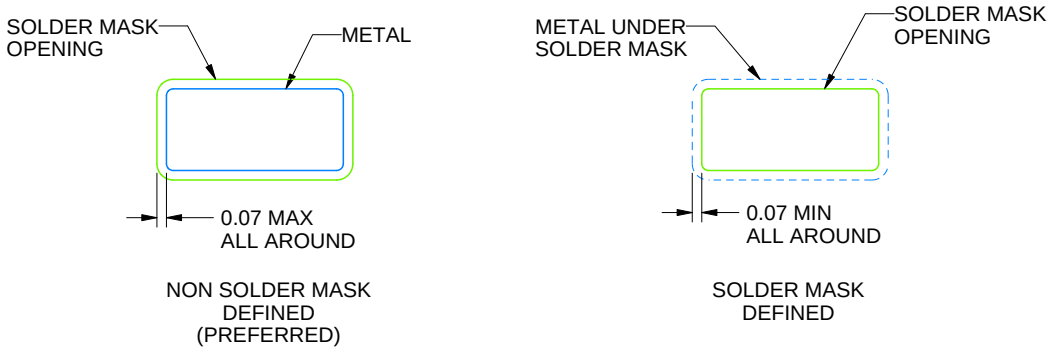
4214838/C 04/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration TO-236, except minimum foot length.



LAND PATTERN EXAMPLE
SCALE:15X

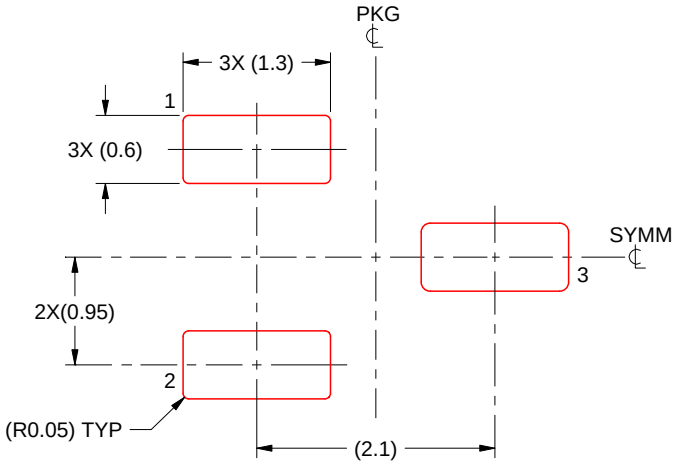


SOLDER MASK DETAILS

4214838/C 04/2017

NOTES: (continued)

4. Publication IPC-7351 may have alternate designs.
5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



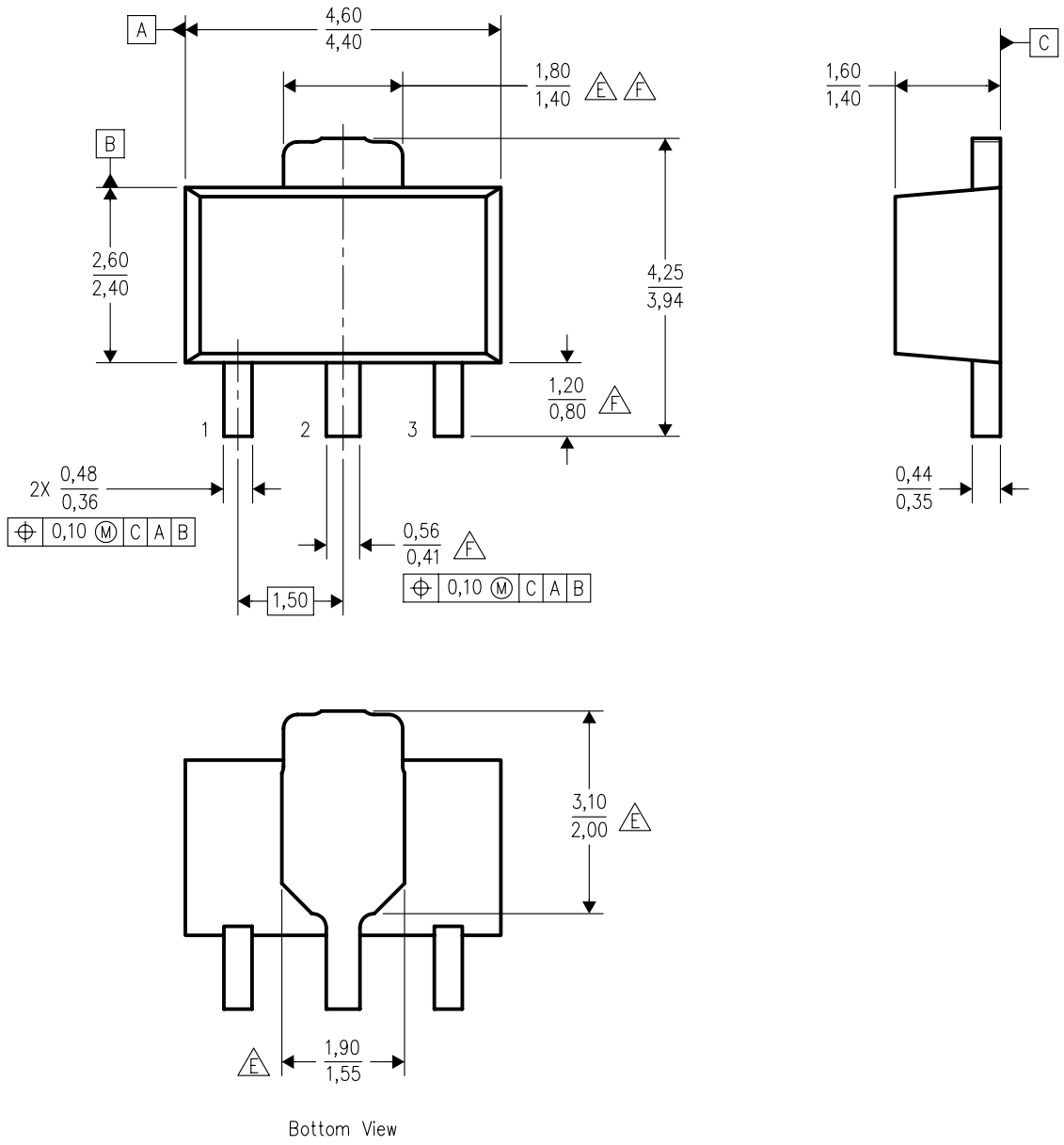
SOLDER PASTE EXAMPLE
BASED ON 0.125 THICK STENCIL
SCALE:15X

4214838/C 04/2017

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
7. Board assembly site may have different recommendations for stencil design.

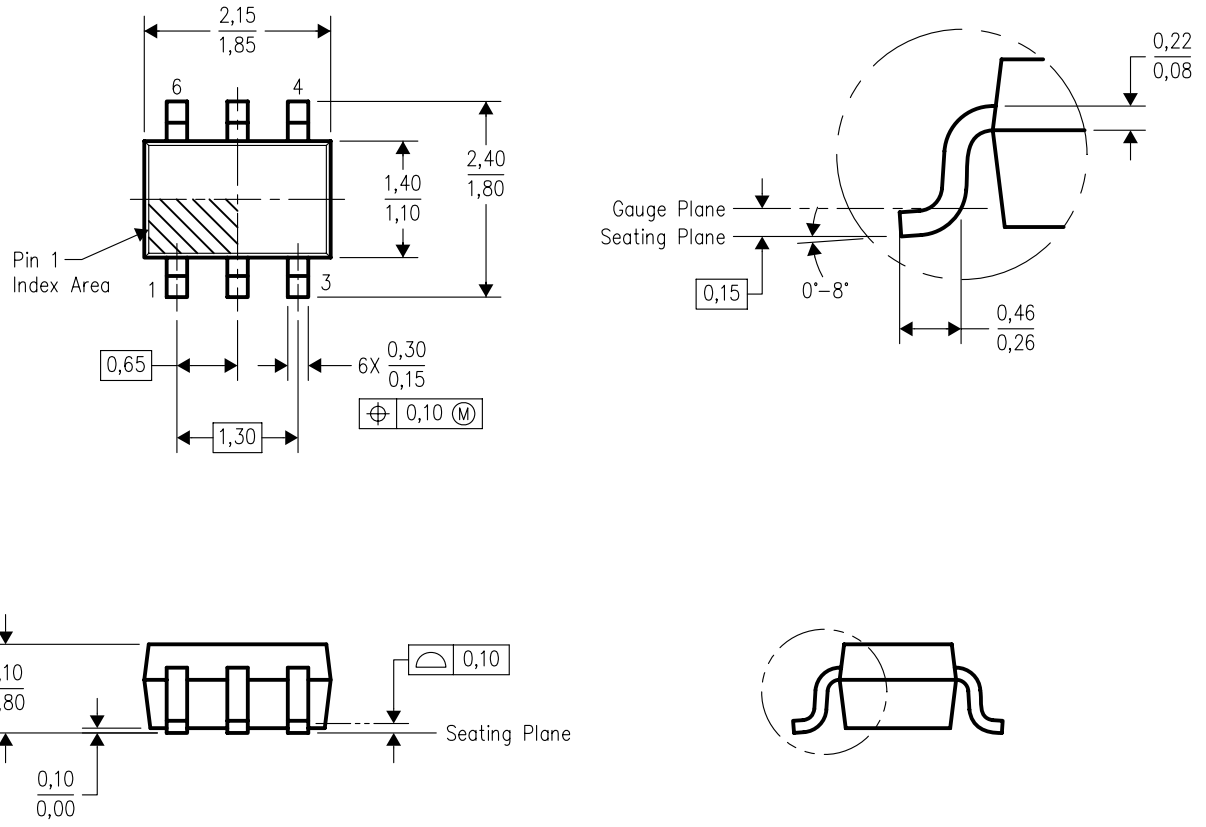
PK (R–PSSO–F3) PLASTIC SINGLE–IN–LINE PACKAGE



4040234/D 02/2006

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. The center lead is in electrical contact with the tab.
D. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion not to exceed 0.15 per side.
E. Thermal pad contour optional within these dimensions.
F. Falls within JEDEC TO–243 variation AA, except minimum lead length, pin 2 minimum lead width, minimum tab width.

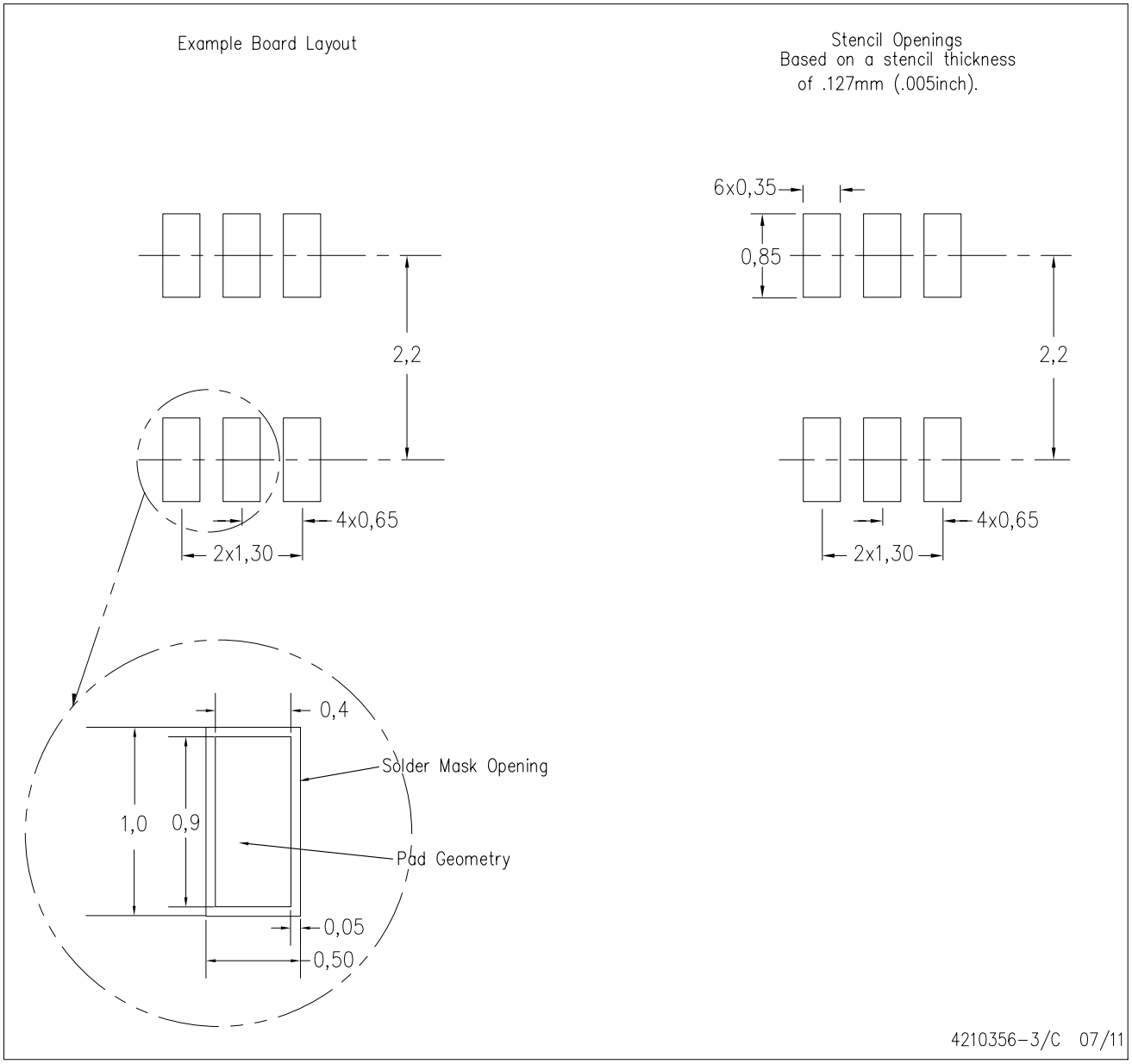
DCK (R–PDSO–G6) PLASTIC SMALL–OUTLINE PACKAGE



4093553–4/G 01/2007

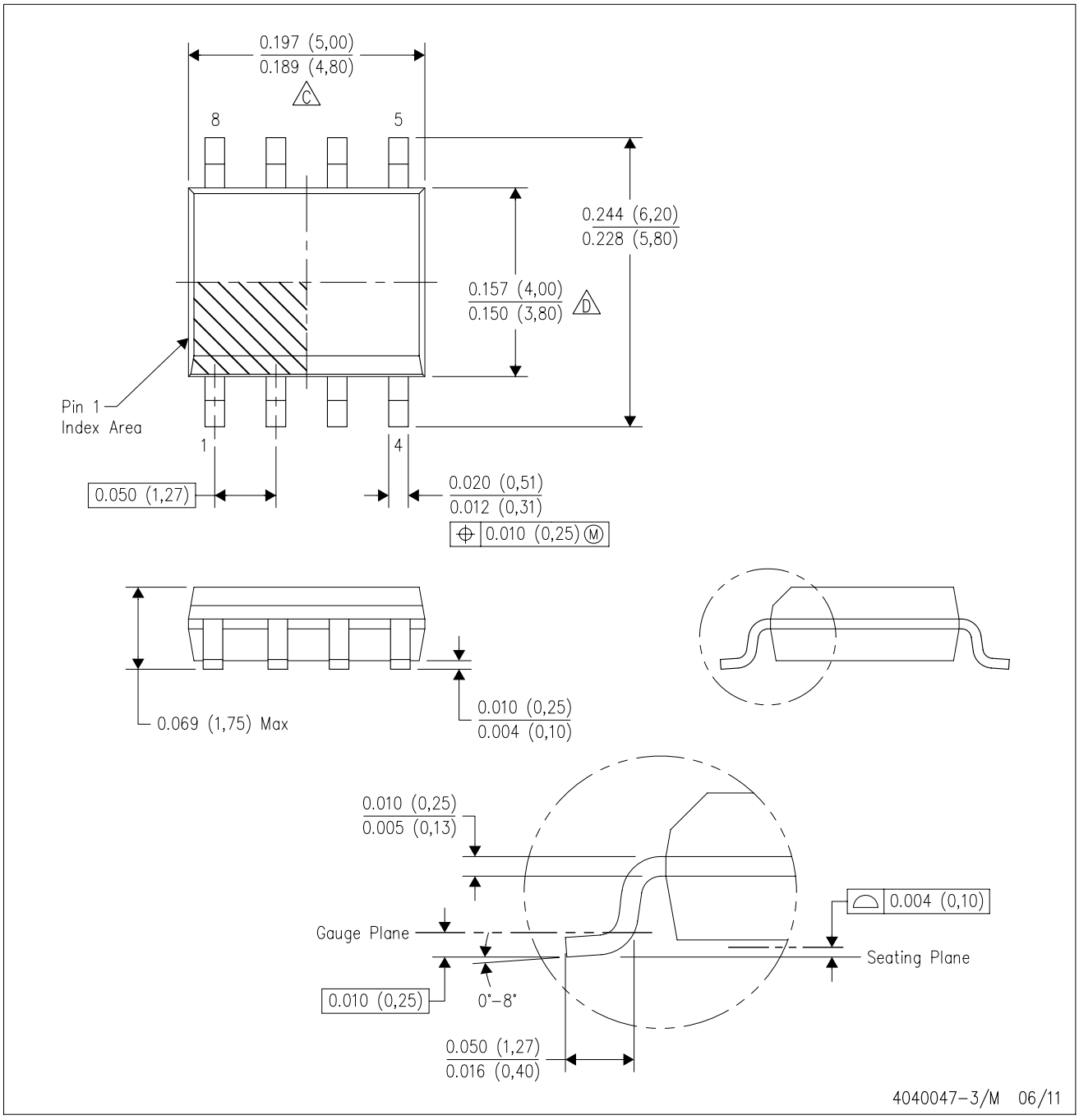
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
D. Falls within JEDEC MO–203 variation AB.

DCK (R–PDSO–G6) PLASTIC SMALL OUTLINE



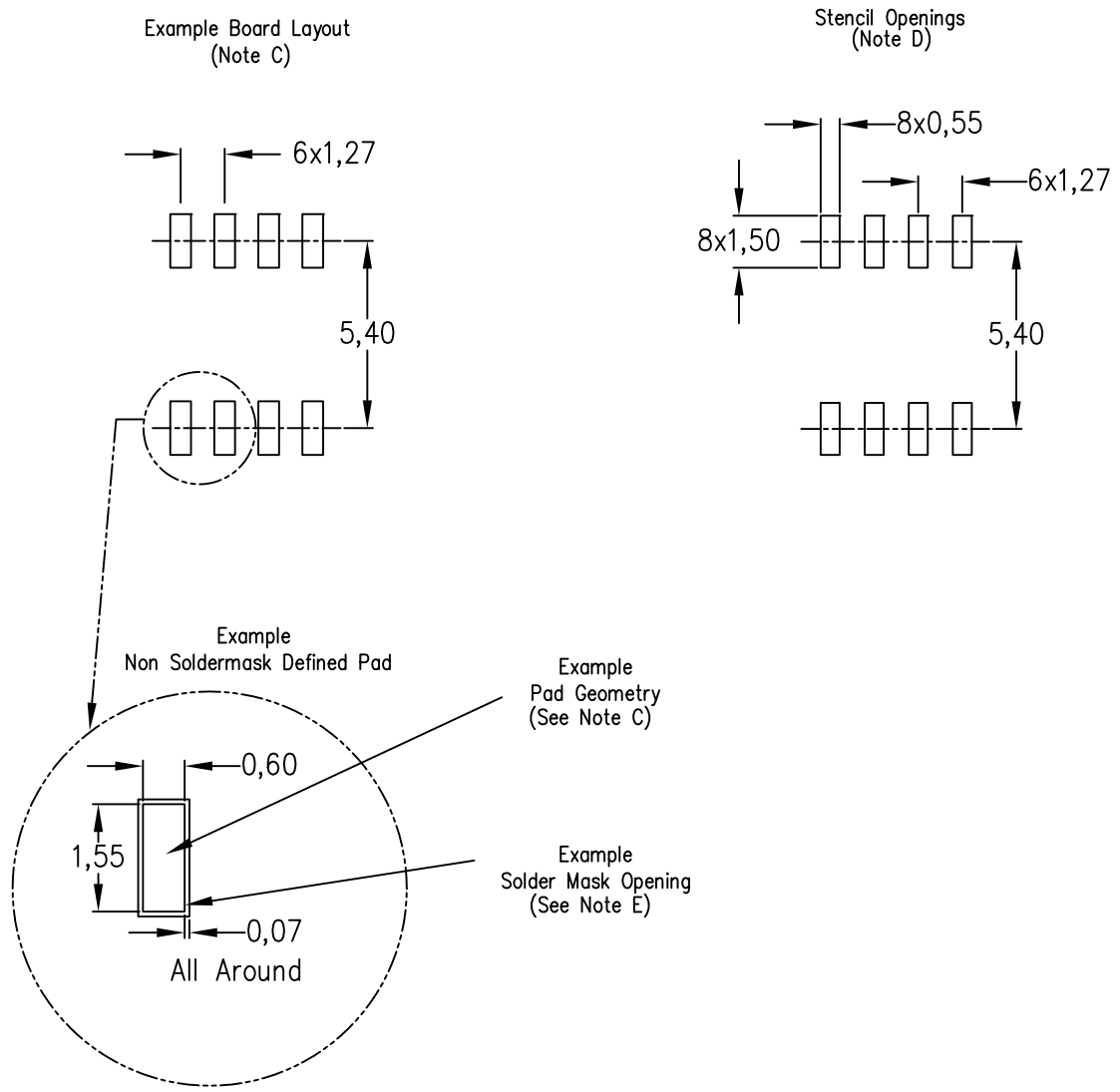
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
D. Publication IPC–7351 is recommended for alternate designs.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC–7525 for other stencil recommendations.

D (R–PDSO–G8) PLASTIC SMALL OUTLINE



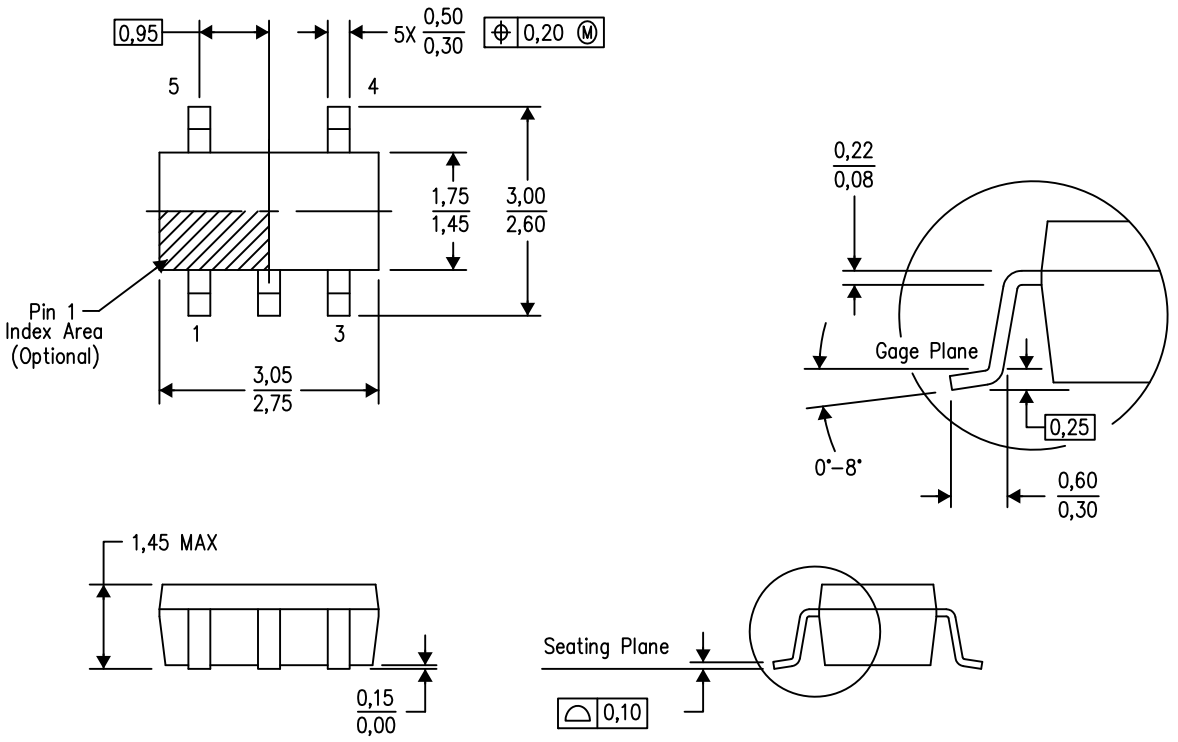
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AA.

D (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

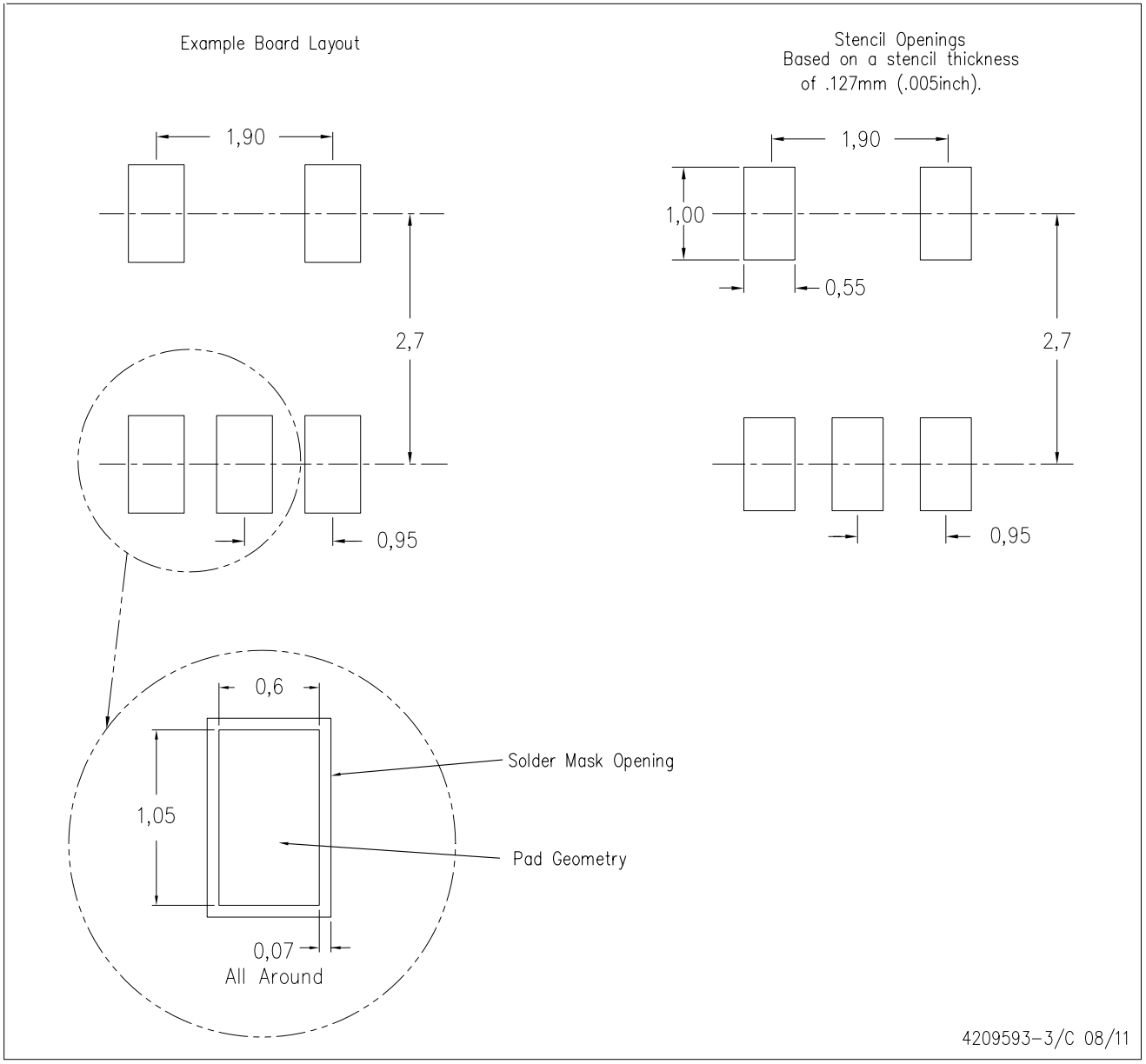
DBV (R–PDSO–G5) PLASTIC SMALL–OUTLINE PACKAGE



4073253–4/N 12/14

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
D. Falls within JEDEC MO–178 Variation AA.

DBV (R–PDSO–G5) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
D. Publication IPC–7351 is recommended for alternate designs.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC–7525 for other stencil recommendations.

GENERIC PACKAGE VIEW

LP 3 TO-92 - 5.34 mm max height

TRANSISTOR OUTLINE

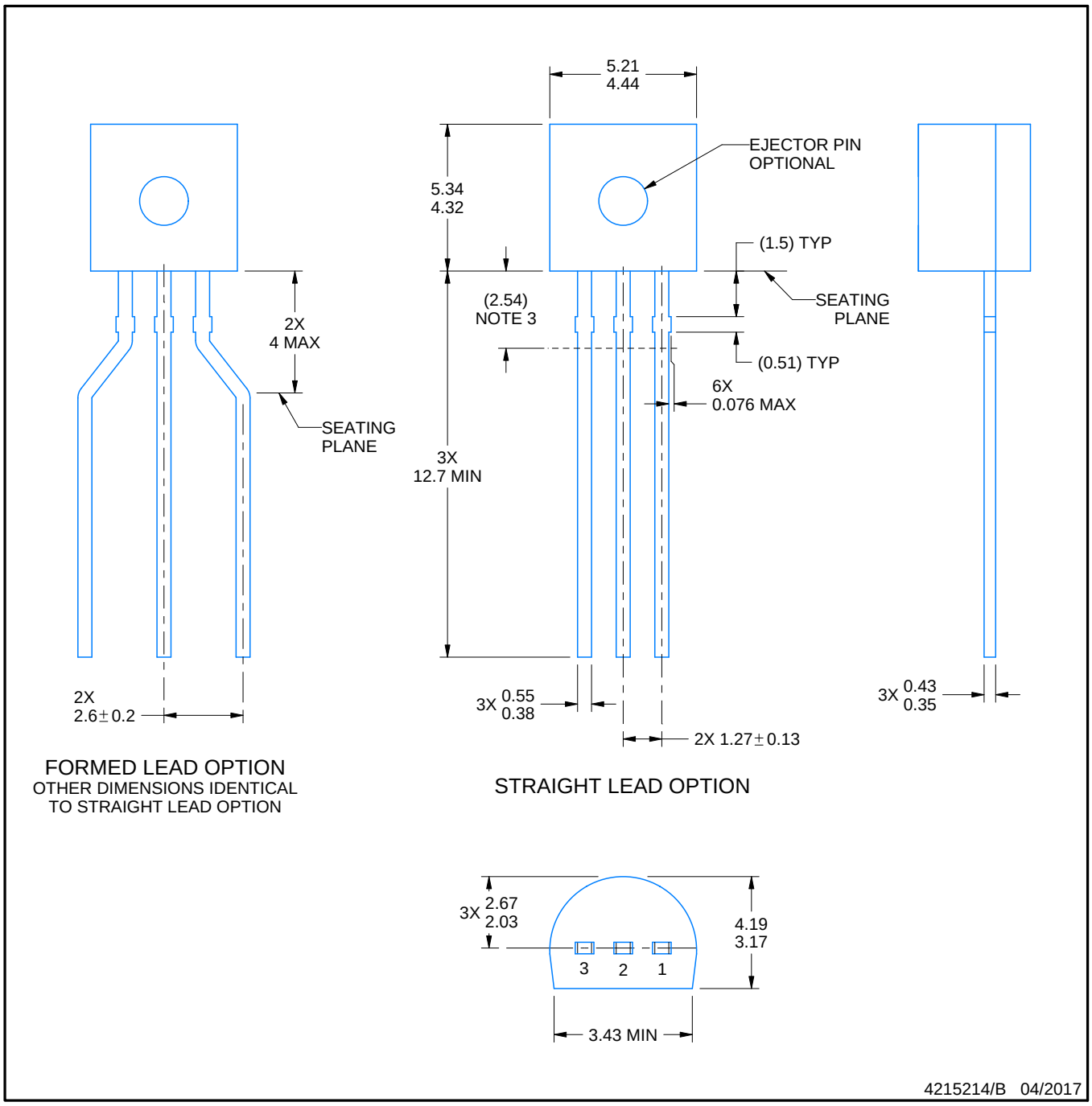
Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

LP0003A

PACKAGE OUTLINE

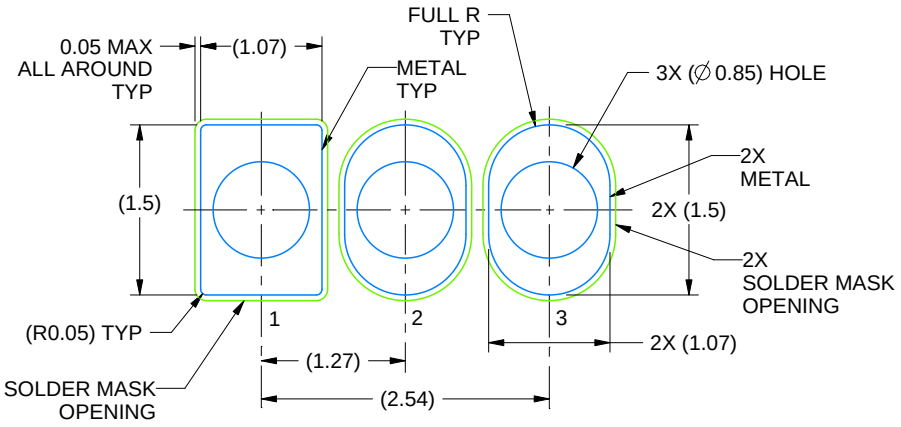
TO-92 - 5.34 mm max height

TO-92

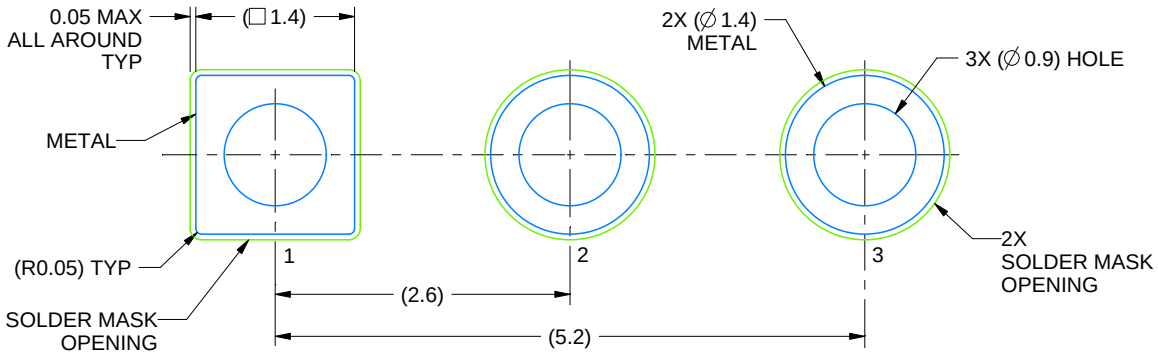


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Lead dimensions are not controlled within this area.
4. Reference JEDEC TO-226, variation AA.
5. Shipping method:
   a. Straight lead option available in bulk pack only.
   b. Formed lead option available in tape and reel or ammo pack.
   c. Specific products can be offered in limited combinations of shipping medium and lead options.
   d. Consult product folder for more information on available options.



LAND PATTERN EXAMPLE
STRAIGHT LEAD OPTION
NON-SOLDER MASK DEFINED
SCALE:15X



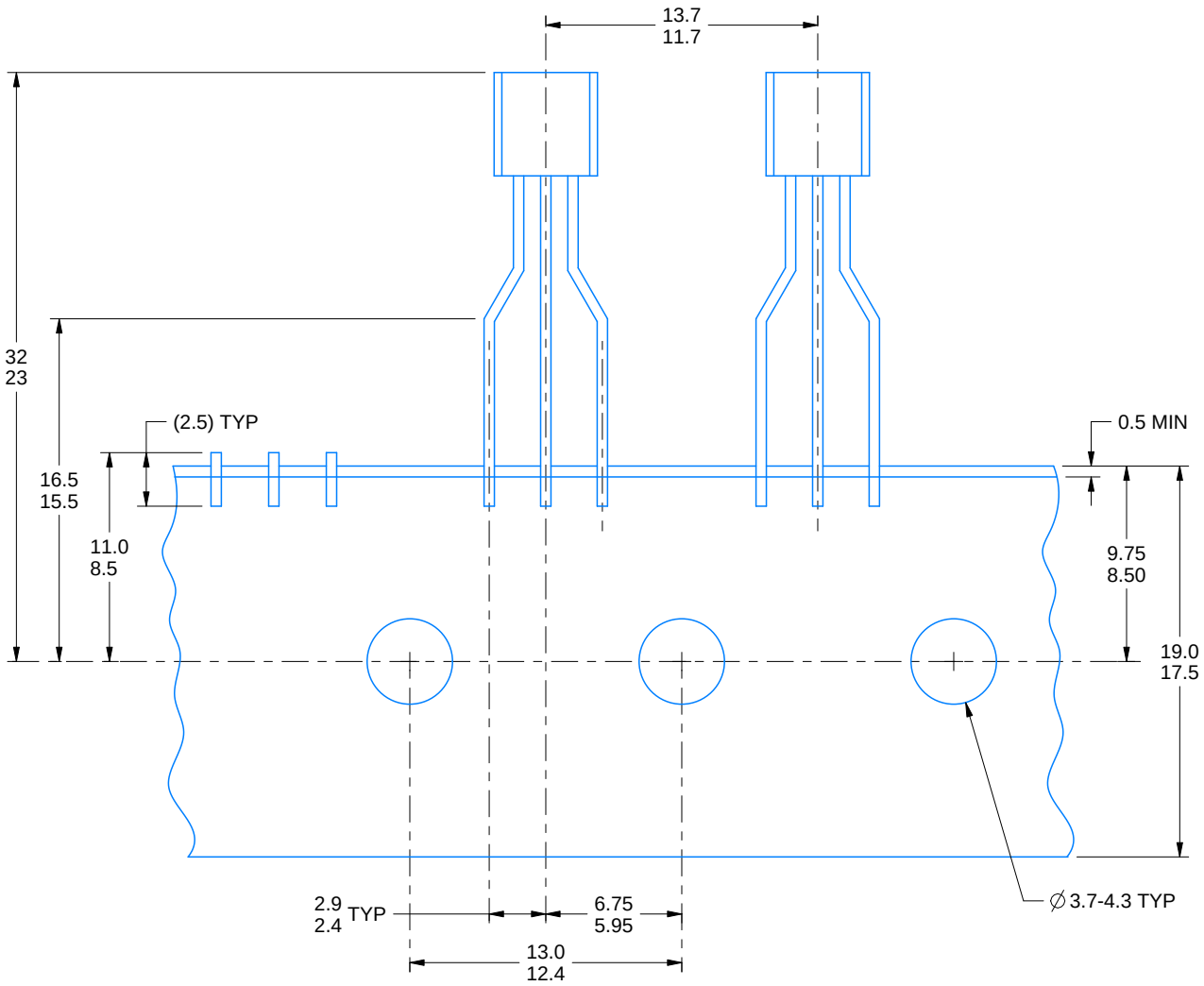
LAND PATTERN EXAMPLE
FORMED LEAD OPTION
NON-SOLDER MASK DEFINED
SCALE:15X

4215214/B 04/2017

LP0003A

TO-92 - 5.34 mm max height

TO-92



FOR FORMED LEAD OPTION PACKAGE

4215214/B 04/2017

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